

正基科技股份有限公司

SPECIFICATION

PRODUCT NAME : AP6676SDSR

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Customer APPROVED	
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正基科技股份有限公司



AP6676SDSR Data Sheet

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Revision

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0.1	2023/09/14	- Preliminary	Ali
1.0	2024/05/29	- Modify Package Information	Ali
1.1	2024/06/13	- Update pin assignment	Ali
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1.4	2025/04/27	- Modify Package Information	Ali
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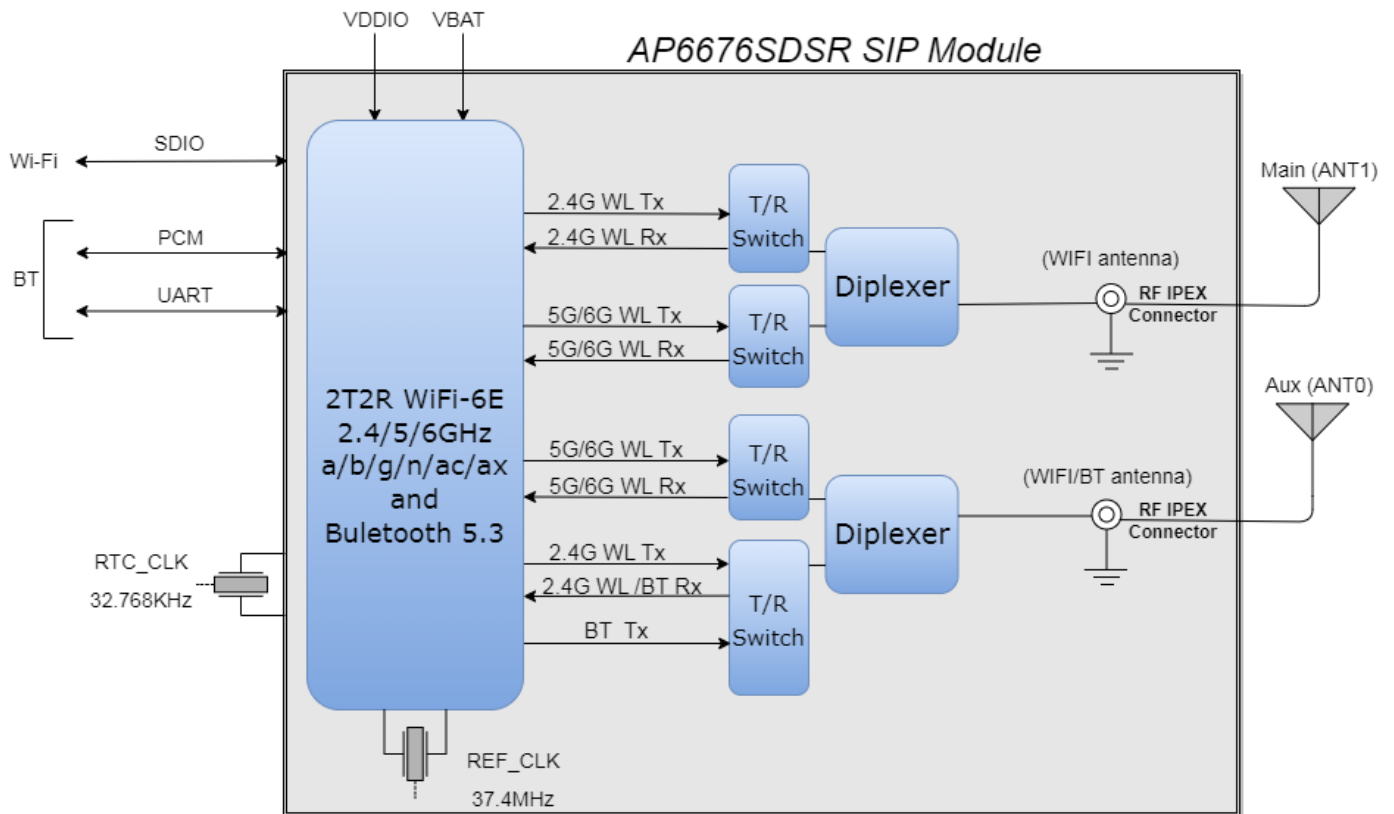
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1. Introduction

1.1 Overview

The AMPAK Technology® AP6676SDSR is a fully Wi-Fi 6E (2.4/5/6GHz) and Bluetooth functionalities module with seamless roaming capabilities and advance security, also it could interact with different vendors' 802.11a/b/g/n/ac/ax 2x2 Access Points with MIMO standard and can accomplish up to speed of 1200Mbps with dual stream in 802.11ax to connect the wireless LAN. Furthermore AP6676SDSR included SDIO interface for Wi-Fi, UART/ PCM interface for Bluetooth.

In addition, this compact module is a total solution for a combination of Wi-Fi + BT technologies. The module is specifically developed for tablet, OTT box and portable devices.



1.2 Product Features

IEEE 802.11 Key Features

- Lead Free design which is compliant with ROHS requirements.
- TX and RX low-density parity check (LDPC) support for improved range and power efficiency.
- Dual-stream spatial multiplexing up to 1200 Mbps data rate.
- 20/40/80 MHz channels for 5GHz and 6GHz radio, and 20MHz channels for 2.4GHz radio.
- Client MU-MIMO.
- Supports 2 antennas with two for shared BT and WLAN port.
- Supports standard SDIO v3.0, compatible with SDIO v2.0 HOST interfaces.

Bluetooth Key Features

- BT host digital interface:
 - HCI UART (up to 4 Mbps)
 - PCM for audio data
 - Complies with Bluetooth Core Specification Version 5.3 with provisions for supporting future specifications. With Bluetooth Class 1 or Class2 transmitter operation.
 - Supports extended synchronous connections (eSCO), for enhanced voice quality by allowing for retransmission of dropped packets.
 - Adaptive frequency hopping (AFH) for reducing radio frequency interference.
- A simplified block diagram of the module is depicted in the figure above.
- BT Core Specification Version 5.3, including the following support:
 - Low energy(LE) isochronous channels
 - LE power control
 - LE enhanced connection update
 - LE channel classification
 - LE audio

2. General Specification

2.1 General Specification

Model Name	AP6676SDSR
Product Description	2T2R 802.11 ax/ac/a/b/g/n Wi-Fi 6E + BT 5.3 Module
Dimension	L x W: 12 x 16(typical) mm H: 1.8(Maximum) mm
WiFi Interface	Support SDIO V3.0/2.0
BT Interface	UART / PCM
Operating temperature	-30°C to +85°C
Storage temperature	-40°C to 125°C
Humidity	Operating Humidity 10% to 95% Non-Condensing

Note: The optimal RF performance specified in the data sheet, however, is guaranteed only -10 °C to +55 °C and $3.2V < V_{BAT} < 3.6V$ without derating performance.

2.2 DC Characteristics

2.2.1 Absolute Maximum Ratings

Symbol	Description	Min.	Max.	Unit
V _{BAT}	Input supply Voltage	-0.5	4.5	V
V _{DDIO}	Digital/ Bluetooth/ I/O Voltage	-0.5	2.07	V

2.2.2 Recommended Operating Rating

The module requires two power supplies: VBAT and VDDIO.

Voltage rails	Min.	Typ.	Max.	Unit
VBAT	3.0	3.3	4.8	V
VDDIO	1.68	1.8	1.98	V

VBAT current consumption 1200mA(Peak), when VBAT = 3.3V

The module requires two power supplies: other Digital I/O Pins.

For VDDIO=1.8V	Min.	Max.	Unit
VIH	$0.65 \times VDDIO$	N/A	V
VIL	N/A	$0.4 \times VDDIO$	V
VOH output@2mA	$VDDIO - 0.4$	N/A	V
VOL output@2mA	N/A	0.4	V

3. Wi-Fi RF Specification

3.1 2.4GHz RF Specification

Conditions : VBAT=3.3V ; VDDIO=1.8V ; Temp:25°C

Feature		Description			
WLAN Standard		IEEE 802.11b/g/n/ax & Wi-Fi compliant			
Frequency Range		2.400 GHz ~ 2.4835 GHz (2.4GHz ISM Band)			
Number of Channels		2.4GHz：Ch1 ~ Ch13			
Modulation		802.11b：DQPSK、DBPSK、CCK 802.11 g/n：OFDM_64-QAM、16-QAM、QPSK、BPSK 802.11ax：OFDM_256-QAM、64-QAM、16-QAM、QPSK、BPSK			
MIC declared power		802.11b: 4.0mW/MHz 802.11g:3.0mW/MHz 802.11n(HT20):3.0mW/MHz 802.11ax(HE20):3.0mW/MHz			
Output Power , tolerance ± 1.5 dB					
The transmit EVM quality & spectrum mask are compliant with IEEE 802.11 standard					
802.11b	1Mbps	2Mbps	5.5Mbps	11Mbps	
	19	19	19	19	
802.11g	6、9Mbps	12、18Mbps	24Mbps	36Mbps	48Mbps
	19	19	18.5	18.5	18
	54Mbps				
	17				
802.11n 20MHz	MCS0~2	MCS3	MCS4	MCS5	MCS6
	19	18.5	18.5	18	17
	MCS7				
	16.5				
802.11ax 20MHz	HE0~2	HE3	HE4	HE5	HE6
	19	18.5	18.5	18	17
	HE7	HE8	HE9		
	16.5	16	15.5		
Note: The specifications of RF output power are subject to change to fulfill the safety regulation and requirements in end-user product.					
Sensitivity, tolerance ± 2 dB					
CCK modulation PER ≤ 8%、OFDM modulation PER ≤ 10%					
802.11b	Data Rate	Spec.(dBm)			
	1Mbps	-97			
	2Mbps	-93			
	5.5Mbps	-91			

	11Mbps	-89		
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802.11g SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	6Mbps	-93	24Mbps	-85
	9Mbps	-92	36Mbps	-82
	12Mbps	-91	48Mbps	-78
	18Mbps	-88	54Mbps	-76
802.11g MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	6Mbps	-95	24Mbps	-87
	9Mbps	-94	36Mbps	-84
	12Mbps	-93	48Mbps	-81
	18Mbps	-90	54Mbps	-78
802.11n_20MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-92	MCS4	-81.5
	MCS1	-89	MCS5	-79
	MCS2	-87	MCS6	-76
	MCS3	-84	MCS7	-75
802.11n_20MHz MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-93	MCS5	-80
	MCS1	-92	MCS6	-78
	MCS2	-90	MCS7	-76
	MCS3	-87	MCS8	-72
	MCS4	-83	MCS15	-73
802.11ax_20MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	HE0	-93	HE6	-76
	HE1	-89	HE7	-76
	HE2	-87	HE8	-72
	HE3	-84	HE9	-70
	HE4	-81.5		
	HE5	-79		
Maximum Input Level	802.11b : -10 dBm			
	802.11g/n/ax : -20 dBm			

3.2 5GHz RF Specification

Conditions : VBAT=3.3V ; VDDIO=1.8V ; Temp:25°C

Feature	Description
WLAN Standard	IEEE 802.11a/n/ac/ax & Wi-Fi compliant
Frequency Range	5.15~5.35GHz 、 5.47~5.725GHz 、 5.725~5.85GHz (5GHz UNII Band)
Number of Channels	5.15~5.35GHz : Ch36 ~ Ch64 5.47~5.725GHz : Ch100 ~ Ch144 5.745~5.85GHz : Ch149 ~ Ch165
Modulation	802.11a : OFDM_64-QAM 、 16-QAM 、 QPSK 、 BPSK 802.11n : OFDM_64-QAM 、 16-QAM 、 QPSK 、 BPSK 802.11ac : OFDM_256-QAM 、 OFDM_64-QAM 、 16-QAM 、 QPSK 、 BPSK 802.11ax : OFDM_1024-QAM 、 OFDM_256-QAM 、 OFDM_64-QAM 、 16-QAM 、 QPSK 、 BPSK
MIC declared power(W52)	802.11a:1.0mW/MHz 802.11n(HT20):1.0mW/MHz 802.11n(HT40):1.0mW/MHz 802.11ac(VHT20):2.0mW/MHz 802.11ac(VHT40):1.0mW/MHz 802.11ac(VHT80):0.5mW/MHz 802.11ax(HE20):1.5mW/MHz 802.11ax(HE40):1.0mW/MHz 802.11ax(HE80):0.3mW/MHz
MIC declared power(W53)	802.11a:1.0mW/MHz 802.11n(HT20):1.0mW/MHz 802.11n(HT40):0.5mW/MHz 802.11ac(VHT20):1.0mW/MHz 802.11ac(VHT40):0.5mW/MHz 802.11ac(VHT80):0.5mW/MHz 802.11ax(HE20):1.0mW/MHz 802.11ax(HE40):0.5mW/MHz 802.11ax(HE80):0.3mW/MHz
MIC declared power(W56)	802.11a:1.5mW/MHz 802.11n(HT20):2.0mW/MHz 802.11n(HT40):2.0mW/MHz 802.11ac(VHT20):2.0mW/MHz 802.11ac(VHT40):2.0mW/MHz 802.11ac(VHT80):1.5mW/MHz 802.11ax(HE20):2.0mW/MHz 802.11ax(HE40):1.5mW/MHz

802.11ax(HE80):0.3mW/MHz

Output Power , tolerance ± 2 dB**The transmit EVM quality & spectrum mask are compliant with IEEE 802.11 standard**

802.11a	Frequency (MHz)	6~9Mbps	12~18Mbps	24Mbps	36Mbps
	5150~5350	16	16	15.5	15.5
	5470~5725	16	16	15.5	15.5
	5745~5845	16	16	15.5	15.5
	Frequency (MHz)	48Mbps	54Mbps		
	5150~5350	15.5	15		
	5470~5725	15.5	15		
	5745~5845	15.5	15		
802.11n 20MHz	Frequency (MHz)	MCS0~2	MCS3	MCS4	MCS5
	5150~5350	16	16	15.5	15.5
	5470~5725	16	16	15.5	15.5
	5745~5845	16	16	15.5	15.5
	Frequency (MHz)	MCS6	MCS7		
	5150~5350	15	14.5		
	5470~5725	15	14.5		
	5745~5845	15	14.5		
802.11n 40MHz	Frequency (MHz)	MCS0~2	MCS3	MCS4	MCS5
	5150~5350	15.5	15.5	15	15
	5470~5725	15.5	15.5	15	15
	5745~5845	15.5	15.5	15	15
	Frequency (MHz)	MCS6	MCS7		
	5150~5350	14.5	14		
	5470~5725	14.5	14		
	5745~5845	14.5	14		
802.11ac 20MHz	Frequency (MHz)	MCS0~2	MCS3	MCS4	MCS5
	5150~5350	16	16	15.5	15.5
	5470~5725	16	16	15.5	15.5
	5745~5845	16	16	15.5	15.5
	Frequency (MHz)	MCS6	MCS7	MCS8	
	5150~5350	15	14.5	12	
	5470~5725	15	14.5	12	
	5745~5845	15	14.5	12	
802.11ac 40MHz	Frequency (MHz)	MCS0~2	MCS3	MCS4	MCS5
	5150~5350	15.5	15.5	15	15
	5470~5725	15.5	15.5	15	15

	5745~5845	15.5	15.5	15	15
	Frequency (MHz)	MCS6	MCS7	MCS8	MCS9
	5150~5350	14.5	14	12	10
	5470~5725	14.5	14	12	10
	5745~5845	14.5	14	12	10
802.11ac 80MHz	Frequency (MHz)	MCS0~2	MCS3	MCS4	MCS5
	5150~5350	15.5	15	14.5	14.5
	5470~5725	15.5	15	14.5	14.5
	5745~5845	15.5	15	14.5	14.5
	Frequency (MHz)	MCS6	MCS7	MCS8	MCS9
	5150~5350	14	14	10	10
	5470~5725	14	14	10	10
	5745~5845	14	14	10	10

802.11ax 20MHz	Frequency (MHz)	HE0~2	HE3	HE4	HE5
	5150~5350	16	15.5	15.5	15.5
	5470~5725	16	15.5	15.5	15.5
	5745~5845	16	15.5	15.5	15.5
	Frequency (MHz)	HE6	HE7	HE8	HE9
	5150~5350	14.5	14.5	12	12
	5470~5725	14.5	14.5	12	12
	5745~5845	14.5	14.5	12	12
	Frequency (MHz)	HE10	HE11		
	5150~5350	10	10		
	5470~5725	10	10		
	5745~5845	10	10		
802.11ax 40MHz	Frequency (MHz)	HE0~2	HE3	HE4	HE5
	5150~5350	15.5	15.5	15	15
	5470~5725	15.5	15.5	15	15
	5745~5845	15.5	15.5	15	15
	Frequency (MHz)	HE6	HE7	HE8	HE9
	5150~5350	14.5	14	12	10
	5470~5725	14.5	14	12	10
	5745~5845	14.5	14	12	10
	Frequency (MHz)	HE10	HE11		
	5150~5350	8.5	8.5		
	5470~5725	8.5	8.5		
	5745~5845	8.5	8.5		
802.11ax 80MHz	Frequency (MHz)	HE0~2	HE3	HE4	HE5
	5150~5350	15.5	15	14.5	14.5
	5470~5725	15.5	15	14.5	14.5
	5745~5845	15.5	15	14.5	14.5
	Frequency (MHz)	HE6	HE7	HE8	HE9
	5150~5350	14	14	10	10
	5470~5725	14	14	10	10
	5745~5845	14	14	10	10
	Frequency (MHz)	HE10	HE11		
	5150~5350	8.5	8.5		
	5470~5725	8.5	8.5		
	5745~5845	8.5	8.5		

Note: The specifications of RF output power are subject to change to fulfill the safety regulation and requirements in end-user product.

Sensitivity, tolerance ± 2 dB
OFDM modulation PER $\leq 10\%$

802.11a SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	6Mbps	-90	24Mbps	-83
	9Mbps	-89	36Mbps	-80
	12Mbps	-88	48Mbps	-75
	18Mbps	-86	54Mbps	-73
MIMO802.11a MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	6Mbps	-92	24Mbps	-86
	9Mbps	-91	36Mbps	-83
	12Mbps	-90	48Mbps	-78
	18Mbps	-89	54Mbps	-77
802.11n_20MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-90	MCS4	-79
	MCS1	-88	MCS5	-76
	MCS2	-86	MCS6	-73
	MCS3	-83	MCS7	-71
802.11n_20MHz MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-92	MCS5	-78
	MCS1	-91	MCS6	-76
	MCS2	-89	MCS7	-74
	MCS3	-86	MCS8	-89
	MCS4	-82	MCS15	-70
802.11n_40MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-88	MCS4	-77
	MCS1	-86	MCS5	-72
	MCS2	-83	MCS6	-70
	MCS3	-80	MCS7	-68
802.11n_40MHz MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-88	MCS5	-75
	MCS1	-88	MCS6	-73
	MCS2	-86	MCS7	-71
	MCS3	-83	MCS8	-86
	MCS4	-79	MCS15	-67

802.11ac_20MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-90	MCS5	-75
	MCS1	-88	MCS6	-73
	MCS2	-86	MCS7	-70
	MCS3	-83	MCS8	-68
	MCS4	-79		
802.11ac_20MHz MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0,NSS=1	-92	MCS6,NSS=1	-76
	MCS1,NSS=1	-91	MCS7,NSS=1	-75
	MCS2,NSS=1	-88	MCS8,NSS=1	-72
	MCS3,NSS=1	-85	MCS0,NSS=2	-88
	MCS4,NSS=1	-82	MCS8,NSS=2	-65
	MCS5,NSS=1	-77		
802.11ac_40MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-88	MCS5	-72
	MCS1	-86	MCS6	-70
	MCS2	-83	MCS7	-69
	MCS3	-80	MCS8	-65
	MCS4	-76	MCS9	-63
802.11ac_40MHz MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0,NSS=1	-90	MCS6,NSS=1	-73
	MCS1,NSS=1	-88	MCS7,NSS=1	-72
	MCS2,NSS=1	-86	MCS8,NSS=1	-68
	MCS3,NSS=1	-82	MCS9,NSS=1	-66
	MCS4,NSS=1	-79	MCS0,NSS=2	-86
	MCS5,NSS=1	-77	MCS9,NSS=2	-60
802.11ac_80MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-85	MCS5	-68
	MCS1	-82	MCS6	-67
	MCS2	-79	MCS7	-65
	MCS3	-76	MCS8	-62
	MCS4	-73	MCS9	-60

802.11ac_80MHz MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0,NSS=1	-87	MCS6,NSS=1	-70
	MCS1,NSS=1	-85	MCS7,NSS=1	-68
	MCS2,NSS=1	-82	MCS8,NSS=1	-66
	MCS3,NSS=1	-79	MCS9,NSS=1	-63
	MCS4,NSS=1	-76	MCS0,NSS=2	-83
	MCS5,NSS=1	-71	MCS9,NSS=2	-58
802.11ax_20MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	HE0	-90	HE6	-73
	HE1	-88	HE7	-70
	HE2	-86	HE8	-68
	HE3	-83	HE9	-64
	HE4	-79	HE10	-59
	HE5	-75	HE11	-57
802.11ax_40MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	HE0	-88	HE6	-70
	HE1	-86	HE7	-69
	HE2	-83	HE8	-65
	HE3	-80	HE9	-64
	HE4	-76	HE10	-60
	HE5	-72	HE11	-55
802.11ax_80MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	HE0	-85	HE6	-67
	HE1	-82	HE7	-65
	HE2	-79	HE8	-62
	HE3	-76	HE9	-61
	HE4	-73	HE10	-55
	HE5	-68	HE11	-52
Maximum Input Level	802.11a/n/ac/ax : -30 dBm			

3.3 6GHz RF Specification

Conditions : VBAT=3.3V ; VDDIO=1.8V ; Temp:25°C

Feature		Description			
WLAN Standard		IEEE 802.11ax			
Frequency Range		5.925 ~ 7.125GHz			
Number of Channels		5955~5415MHz : 6G1 ~ 6G93 、 6435~6515MHz : 6G97 ~ 6G113 6535~6855MHz : 6G117 ~ 6G181 、 6875~7115MHz : 6G185 ~ 6G233			
Modulation		802.11ax : OFDMA /1024-QAM 、 256-QAM 、 64-QAM 、 16-QAM 、 QPSK 、 BPSK			
MIC declared power(W56)		802.11ax(HE20):0.5mW/MHz 802.11ax(HE40):0.2mW/MHz 802.11ax(HE80):0.1mW/MHz			
Output Power , tolerance ± 3dB					
The transmit EVM quality & spectrum mask are compliant with IEEE 802.11 standard					
802.11ax 20MHz	Frequency (MHz)	HE0~2	HE3	HE4	HE5
	5955~5415	14.5	14	13.5	13.5
	6435~6515	14.5	14	13.5	13.5
	6535~6855	14.5	14	13.5	13.5
	6875~7115	14.5	14	13.5	13.5
	Frequency (MHz)	HE6	HE7	HE8	HE9
	5955~5415	13.5	13	11	10.5
	6435~6515	13.5	13	11	10.5
	6535~6855	13.5	13	11	10.5
	6875~7115	13.5	13	11	10.5
	Frequency (MHz)	HE10	HE11		
	5955~5415	8.5	8.5		
	6435~6515	8.5	8.5		
	6535~6855	8.5	8.5		
	6875~7115	8.5	8.5		
802.11ax 40MHz	Frequency (MHz)	HE0~2	HE3	HE4	HE5
	5955~5415	14.5	14	13	13
	6435~6515	14.5	14	13	13
	6535~6855	14.5	14	13	13
	6875~7115	14.5	14	13	13
	Frequency (MHz)	HE6	HE7	HE8	HE9
	5955~5415	12.5	12.5	11	9
	6435~6515	12.5	12.5	11	9

	6535~6855	12.5	12.5	11	9
	6875~7115	12.5	12.5	11	9
	Frequency (MHz)	HE10	HE11		
	5955~5415	8	8		
	6435~6515	8	8		
	6535~6855	8	8		
	6875~7115	8	8		
802.11ax 80MHz	Frequency (MHz)	HE0~2	HE3	HE4	HE5
	5955~5415	14.5	14	13	13
	6435~6515	14.5	14	13	13
	6535~6855	14.5	14	13	13
	6875~7115	14.5	14	13	13
	Frequency (MHz)	HE6	HE7	HE8	HE9
	5955~5415	12.5	12.5	11	9
	6435~6515	12.5	12.5	11	9
	6535~6855	12.5	12.5	11	9
	6875~7115	12.5	12.5	11	9
	Frequency (MHz)	HE10	HE11		
	5955~5415	8	8		
	6435~6515	8	8		
	6535~6855	8	8		
	6875~7115	8	8		

Note: The specifications of RF output power are subject to change to fulfill the safety regulation and requirements in end-user product.

Sensitivity, tolerance ± 2 dB, OFDM modulation PER $\leq 10\%$

802.11ax_20MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	HE0	-88	HE6	-71
	HE1	-86	HE7	-68
	HE2	-84	HE8	-66
	HE3	-83	HE9	-62
	HE4	-77	HE10	-57
	HE5	-73	HE11	-55
802.11ax_40MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	HE0	-86	HE6	-68
	HE1	-84	HE7	-67
	HE2	-81	HE8	-63
	HE3	-78	HE9	-62
	HE4	-74	HE10	-68

	HE5	-70	HE11	-53
802.11ax_80MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	HE0	-83	HE6	-65
	HE1	-80	HE7	-63
	HE2	-77	HE8	-60
	HE3	-74	HE9	-59
	HE4	-71	HE10	-55
	HE5	-66	HE11	-51
Maximum Input Level	802.11a/n/ac/ax : -30 dBm			

4. Bluetooth Specification

4.1 Bluetooth Specification

Conditions : VBAT=3.3V ; VDDIO=1.8V ; Temp:25°C

Feature	Description
General Specification	
Bluetooth Standard	BDR 、EDR(2 、3Mbps) 、LE(1Mbps) 、LE2(2Mbps) 、LELR
Host Interface	UART
Frequency Band	2402 MHz ~ 2480 MHz
Number of Channels	79 channels for classic 、40 channels for BLE
Modulation	GFSK, $\pi/4$ -DQPSK, 8DPSK
RF Specification	
Output Power , tolerance ± 2 dB	
MIC (BDR/EDR) Declared power	Normal Operation (79 Channels): 0.1mW/MHz
MIC (BLE) Declared power	Normal Operation (40 Channels): 2.0mW
	CL1 (dBm)
BDR Output Power	7
EDR Output Power	6
BLE Output Power	7
Sensitivity, tolerance ± 2 dB	
Sensitivity @ BER=0.1% for GFSK (1Mbps)	-89 dBm
Sensitivity @ BER=0.01% for $\pi/4$ -DQPSK (2Mbps)	-92 dBm
Sensitivity @ BER=0.01% for 8DPSK (3Mbps)	-84 dBm
Sensitivity @ PER=30.8% for LE (1Mbps)	-92 dBm
Sensitivity @ PER=30.8% for 2LE (2Mbps)	-91 dBm
Maximum Input Level	GFSK (1Mbps):-20dBm

$\pi/4$ -DQPSK (2Mbps) :-20dBm

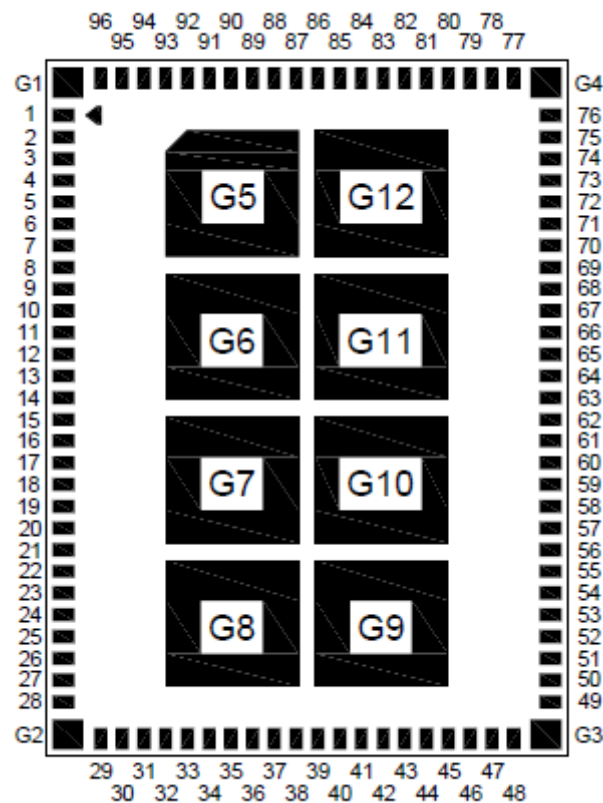
8DPSK (3Mbps) :-20dBm

Note* : The Bluetooth BDR output power is able to be configured by firmware (hcd file).

5. Pin Definition

5.1 Pin Outline

< TOP VIEW >



5.2 Pin Assignment

NO	Name	Type	Description
1	NC	—	Floating (Don't connected to ground)
2	NC	—	Floating (Don't connected to ground)
3	WL_GPIO4	I/O	WLAN GPIO 4
4	VBAT	I	VBAT system power supply input
5	VBAT	I	VBAT system power supply input
6	GND	—	Ground connections
7	WL_GPIO5	I/O	WLAN GPIO 5,option PTA function is GRANT output -Pull low when PTA decides to reserve medium for DECT -Pull high when PTA decides to reserve medium for

			WIFI/BT
8	WL_GPIO8	I/O	WLAN GPIO 8
9	WL_GPIO9	I/O	WLAN GPIO 9
10	NC	—	Floating (Don't connected to ground)
11	NC	—	Floating (Don't connected to ground)
12	ABUCK_1P12	I	Internal Buck voltage generation pin
13	ABUCK_1P12	I	Internal Buck voltage generation pin
14	GND	—	Ground connections
15	ASR_VLX	O	Internal Analog Buck voltage generation pin
16	ASR_VLX	O	Internal Analog Buck voltage generation pin
17	GND	—	Ground connections
18	CSR_VLX	O	Internal Analog Buck voltage generation pin
19	CSR_VLX	O	Internal Analog Buck voltage generation pin
20	GND	—	Ground connections
21	CBUCK_0P9	I	Internal Buck voltage generation pin
22	CBUCK_0P9	I	Internal Buck voltage generation pin
23	GND	—	Ground connections
24	BT_WAKE	I	HOST wake-up Bluetooth device
25	NC	—	Floating (Don't connected to ground)
26	GND	—	Ground connections
27	LPO_IN	I	External Low Power Clock input (32.768KHz)
28	WL_GPIO1	I/O	WLAN GPIO 1/WL_DEV_WAKE
29	NC	—	Floating (Don't connected to ground)
30	NC	—	Floating (Don't connected to ground)
31	NC	—	Floating (Don't connected to ground)
32	GND	—	Ground connections
33	NC	—	Floating (Don't connected to ground)
34	NC	—	Floating (Don't connected to ground)
35	GND	—	Ground connections
36	NC	—	Floating (Don't connected to ground)
37	NC	—	Floating (Don't connected to ground)
38	GND	—	Ground connections
39	NC	—	Floating (Don't connected to ground)
40	NC	—	Floating (Don't connected to ground)
41	GND	—	Ground connections
42	NC	—	Floating (Don't connected to ground)
43	NC	—	Floating (Don't connected to ground)
44	NC	—	Floating (Don't connected to ground)

45	WL_REG_ON	I	Low asserting reset for WiFi core
46	WL_HOST_WAKE	O	WLAN to wake-up HOST
47	SDIO_DATA_3	I/O	SDIO data line 3
48	SDIO_DATA_2	I/O	SDIO data line 2
49	SDIO_DATA_1	I/O	SDIO data line 1
50	SDIO_DATA_0	I/O	SDIO data line 0
51	SDIO_DATA_CMD	I/O	SDIO command line
52	SDIO_DATA_CLK	I/O	SDIO clock line
53	BT_HOST_WAKE	O	Bluetooth device to wake-up HOST
54	BT_UART_CTS	I	Bluetooth UART clear to send
55	BT_UART_TX	O	Bluetooth UART serial data output
56	BT_UART_RX	I	Bluetooth UART serial data input
57	BT_UART_RTS	O	Bluetooth UART request to send
58	PCM_SYNC	I/O	PCM Sync; can be master (output) or slave (input)
59	PCM_IN	I	PCM data input
60	PCM_OUT	O	PCM Data output
61	PCM_CLK	I/O	PCM clock; can be master (output) or slave (input)
62	GND	—	Ground connections
63	BT_REG_ON	I	Low asserting reset for Bluetooth core
64	WL_GPIO2	I/O	WLAN GPIO 2,option PTA function is REQUEST input -Pull low when the traffic ends -Pull high when there is Tx or Rx traffic incoming
65	WL_GPIO3	I/O	WLAN GPIO 3,option PTA function is PRIORITY input -Pull low when the high priority traffic ends -Pull high when the incoming traffic is high priority
66	DBG_UART_RX/WL_GPIO10	I/O	DBG UART Rx , WLAN GPIO 10
67	DBG_UART_TX/WL_GPIO11	I/O	DBG UART Tx , WLAN GPIO 11
68	GND	—	Ground connections
69	NC	—	Floating (Don't connected to ground)
70	NC	—	Floating (Don't connected to ground)
71	GND	—	Ground connections
72	VIO	P	I/O 1.8 Voltage supply input
73	VIO	P	I/O 1.8 Voltage supply input
74	GND	—	Ground connections
75	GND	—	Ground connections
76	GND	—	Ground connections
77	GND	—	Ground connections
78	GND	—	Ground connections
79	GND	—	Ground connections

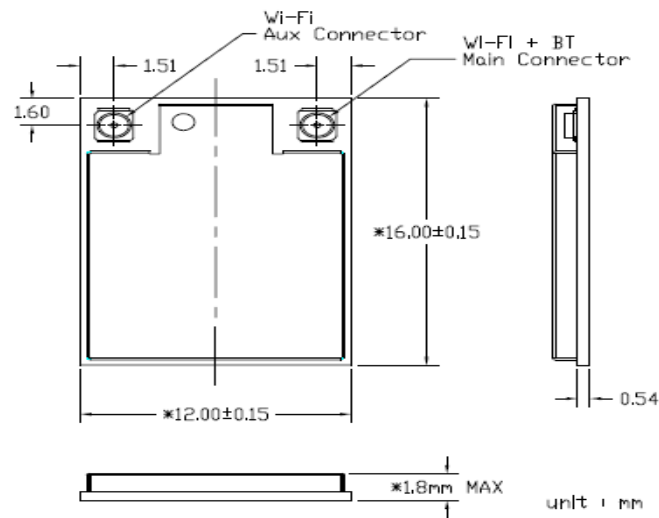
80	GND	—	Ground connections
81	GND	—	Ground connections
82	GND	—	Ground connections
83	GND	—	Ground connections
84	GND	—	Ground connections
85	GND	—	Ground connections
86	GND	—	Ground connections
87	GND	—	Ground connections
88	GND	—	Ground connections
89	GND	—	Ground connections
90	GND	—	Ground connections
91	GND	—	Ground connections
92	GND	—	Ground connections
93	GND	—	Ground connections
94	GND	—	Ground connections
95	GND	—	Ground connections
96	GND	—	Ground connections
G1	GND	—	Ground connections
G2	GND	—	Ground connections
G3	GND	—	Ground connections
G4	GND	—	Ground connections
G5	GND	—	Ground connections
G6	GND	—	Ground connections
G7	GND	—	Ground connections
G8	GND	—	Ground connections
G9	GND	—	Ground connections
G10	GND	—	Ground connections
G11	GND	—	Ground connections
G12	GND	—	Ground connections

6. Dimensions

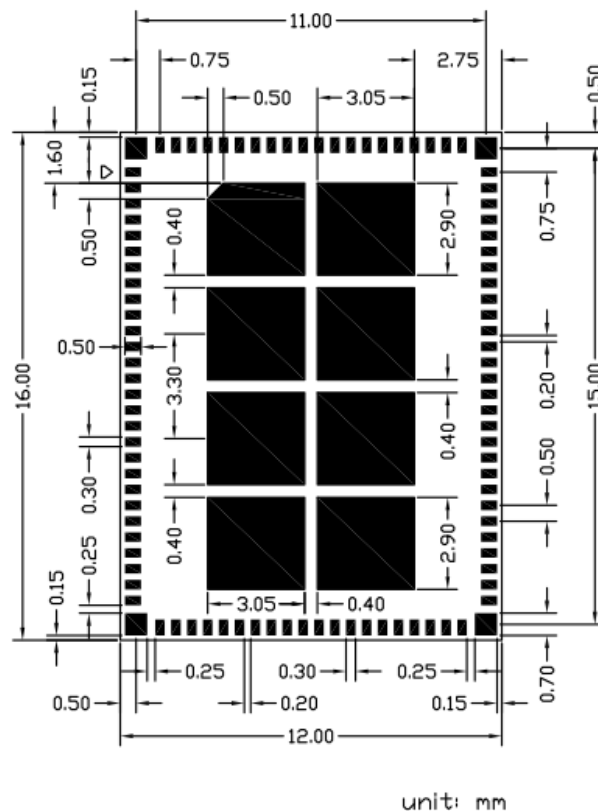
6.1 Module Dimensions

(Unit: mm)

< TOP VIEW >



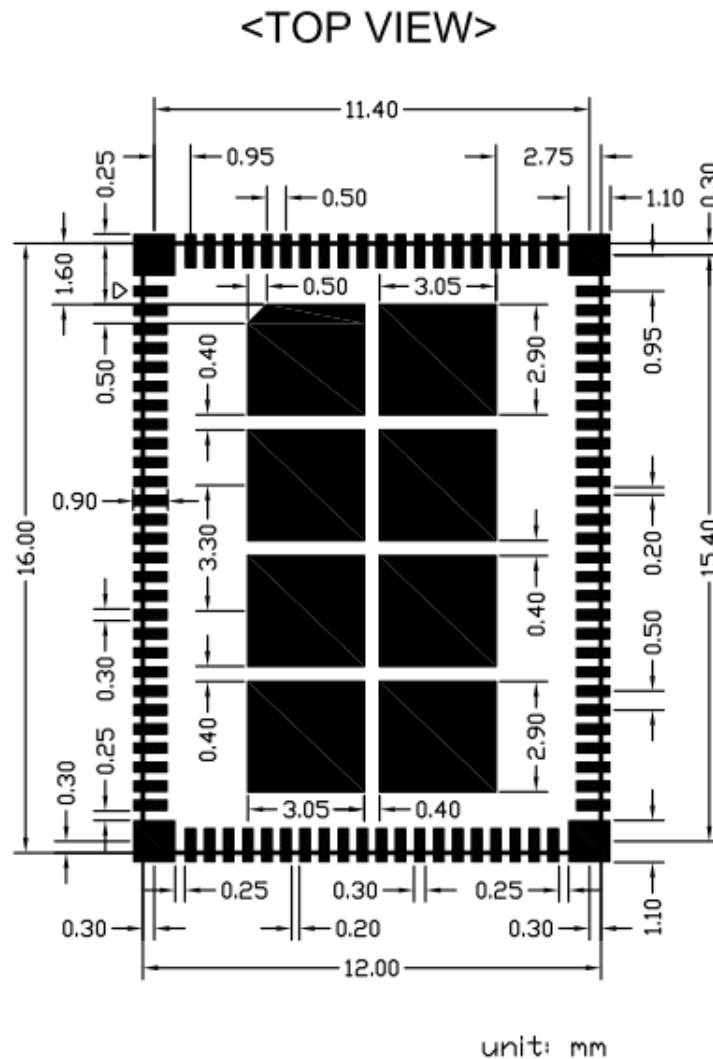
< TOP VIEW >



unit: mm
GENERAL TOLERANCE IS ± 0.10 mm
UNLESS OTHERWISE SPECIFIED

6.2 Recommended footprint

(Unit: mm)



- Solder paste layer design is generally the same as recommended footprint.
(錫膏層設計通常建議和焊墊尺寸相同)
- If soldering quality with good wetting on upright side is essential for PQC, how to optimize the aperture design in the stencil to adjust the amount of solder paste would be crucial.
In addition, a kind of stencil design with stepped thickness in partial area would be considered if the thickness of stencil is about 0.1mm or thinner. Please optimize the stencil design by manufacture engineer or contact AMPAK FAE for assistance.
(如果模組吃錫品質考量側面爬錫，如何優化鋼網開孔設計以調整適當的錫膏量是非常重要的。尤其鋼網的厚度大約是 0.1mm 或更薄時，可考慮局部加厚鋼網的設計。請諮詢製程工程師以優化鋼網的設計,或是聯絡正基科技技術支持團隊).

7. Host Interface Timing Diagram

7.1 Power-up Sequence Timing Diagram

The module has signals that allow the host to control power consumption by enabling or disabling the Bluetooth, WLAN and internal regulator blocks. These signals are described below.

Additionally, diagrams are provided to indicate proper sequencing of the signals for various operating states.

The timing value indicated are minimum required values: longer delays are also acceptable.

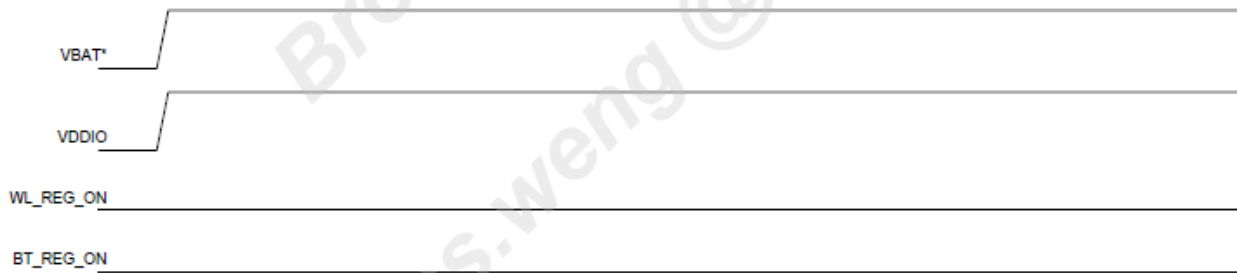
- **WL_REG_ON:** This signal is used by the PMU to power up the WLAN section. It is also OR-gated with the BT_REG_ON input to control the internal regulators. When this pin is high, the regulators are enabled and the WLAN section is out of reset. When this pin is low, the WLAN section is in reset. If BT_REG_ON and WL_REG_ON are both low, the regulators are disabled.
- **BT_REG_ON:** This signal is used by the PMU to decide whether or not to power down the internal regulators. If BT_REG_ON and WL_REG_ON are low, the regulators will be disabled.
- It suggests customers connect WL_REG_ON and BT_REG_ON to GPIOs for control, otherwise unexpected errors may occur when boot-up the device.
- In the figure, The VDDIO power supply has been included in the module. When VBAT is power-up, VDDIO will rise to high level after 15 ms.
- The module main chip has an internal power-on reset (POR) circuit. The device will be held in reset for a maximum of 110 ms after VDDC and VDDIO have both passed the POR threshold. Wait at least 150 ms after VDDC and VDDIO are available before initiating PCIe accesses.



***Notes:**

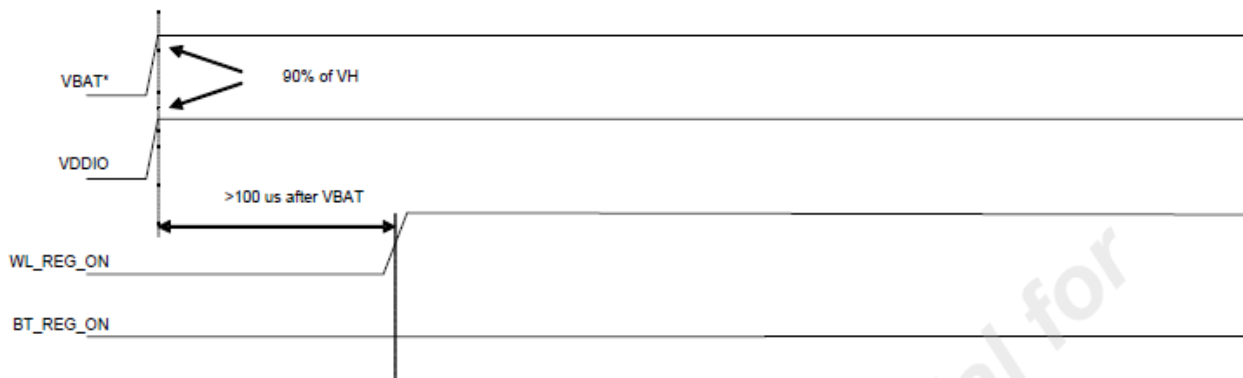
1. The VBAT and VDDIO 10%–90% rise-time slopes must be greater than 50 microseconds/V.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

WLAN=ON, Bluetooth=ON

***Notes:**

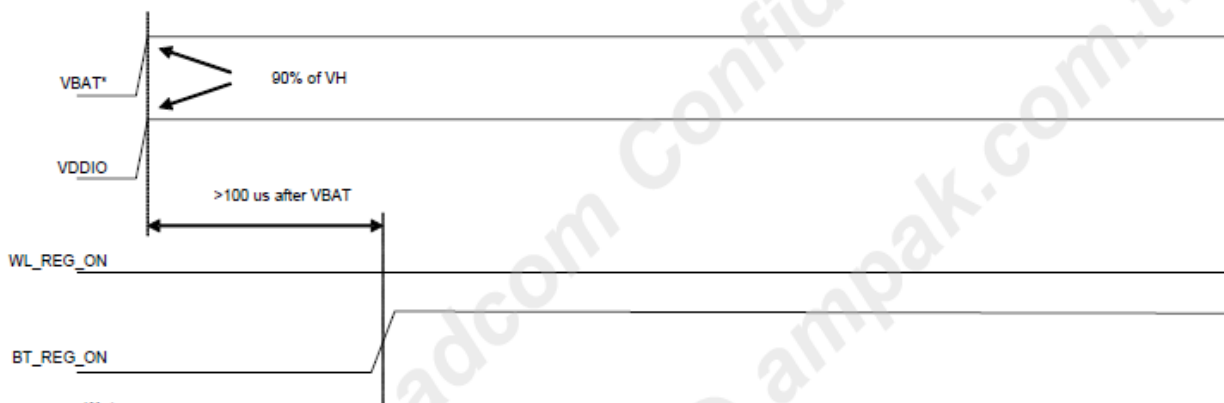
1. The VBAT and VDDIO 10%–90% rise-time slopes must be greater than 50 microseconds/V.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

WLAN=OFF, Bluetooth=OFF

***Notes:**

1. The VBAT and VDDIO 10%–90% rise-time slopes must be greater than 50 microseconds/V.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

WLAN=ON, Bluetooth=OFF

***Notes:**

1. The VBAT and VDDIO 10%–90% rise-time slopes must be greater than 50 microseconds/V.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

WLAN=OFF, Bluetooth=ON

7.2 SDIO Interface Description

The module WLAN section provides support for SDIO version 3.0 at 1.8V signaling, including the new UHS-1 mode:

DS : Default speed (DS) up to 25MHz, including 1- and 4-bit modes.

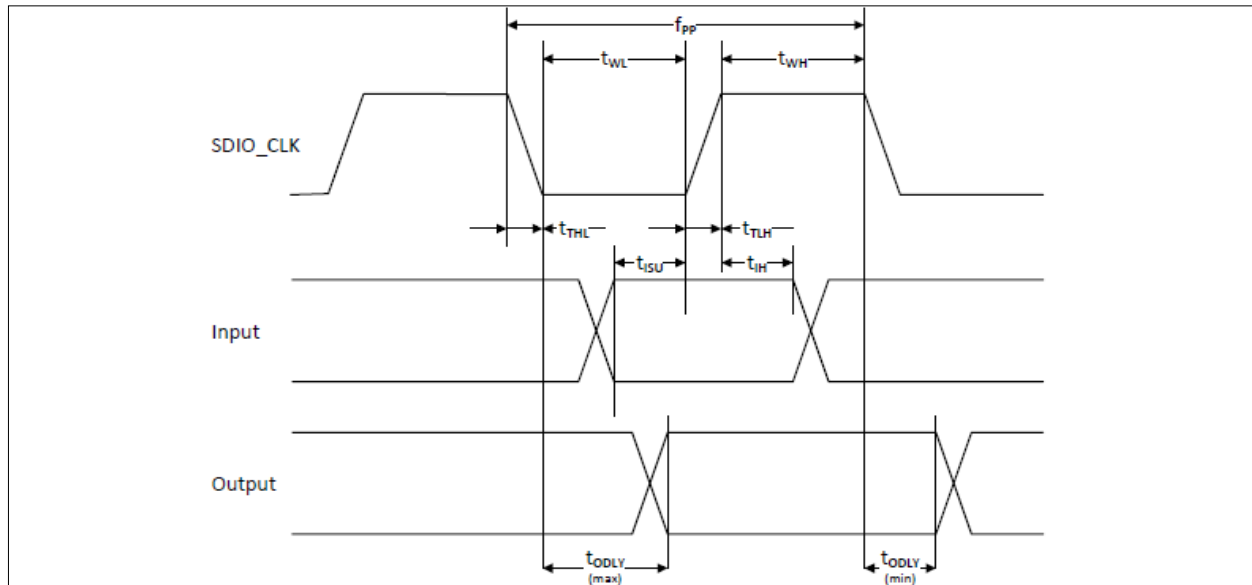
- SDR12 : SDR up to 25 MHz
- SDR25 : SDR up to 50MHz
- SDR50 : SDR up to 100MHz
- SDR104 : SDR up to 208MHz
- DDR50 : DDR up to 50MHz

Noted : The AP6676SDSR is backward compatible with SDIO V2.0 host interfaces.

SDIO Pin Description

SD 4-Bit Mode		SD 1-Bit Mode	
DATA0	Data Line 0	DATA	Data line
DATA1	Data Line 1 or Interrupt	IRQ	Interrupt
DATA2	Data Line 2 or Read Wait	RW	Read Wait
DATA3	Data Line 3	N/C	Not used
CLK	Clock	CLK	Clock
CMD	Command Line	CMD	Command Line

SDIO Default Mode Timing Diagram



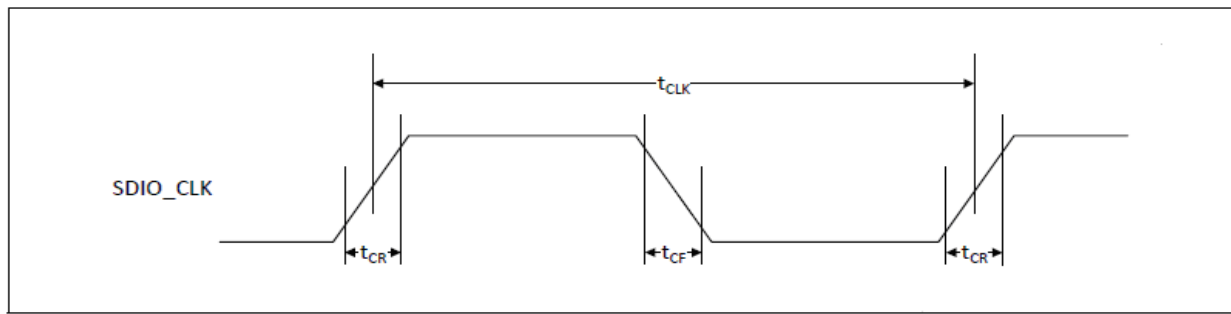
Parameter	Symbol	Minimum	Typical	Maximum	Unit
SDIO CLK (All values are referred to minimum V_{IH} and maximum V_{IL}^b)					
Frequency – Data Transfer mode	f_{PP}	0	–	25	MHz
Frequency – Identification mode	f_{OD}	0	–	400	kHz
Clock low time	t_{WL}	10	–	–	ns
Clock high time	t_{WH}	10	–	–	ns
Clock rise time	t_{TLH}	–	–	10	ns
Clock low time	t_{THL}	–	–	10	ns
Inputs: CMD, DAT (referenced to CLK)					
Input setup time	t_{ISU}	5	–	–	ns
Input hold time	t_{IH}	5	–	–	ns
Outputs: CMD, DAT (referenced to CLK)					
Output delay time – Data Transfer mode	t_{ODLY}	0	–	14	ns
Output delay time – Identification mode	t_{ODLY}	0	–	50	ns

a. Timing is based on $CL \leq 40pF$ load on CMD and Data.

b. $\min(V_{IH}) = 0.7 \times V_{DDIO}$ and $\max(V_{IL}) = 0.2 \times V_{DDIO}$.

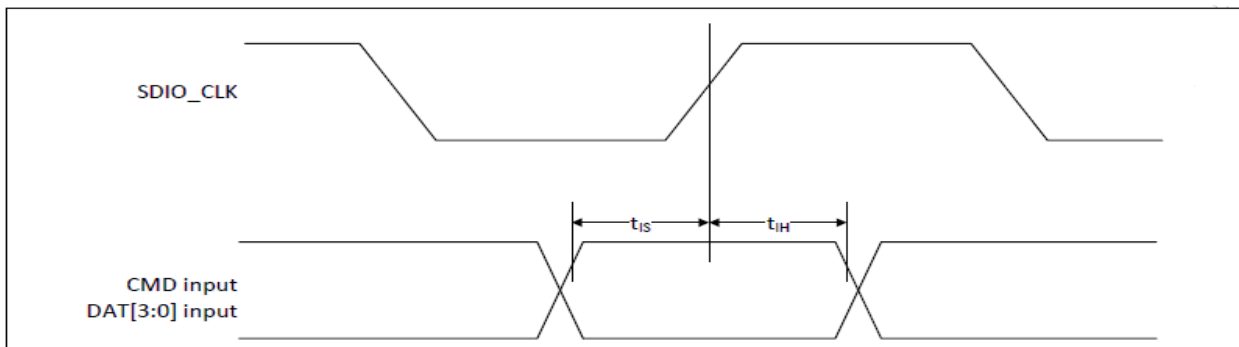
SDIO Bus Timing Specifications in SDR Modes

Clock timing (SDR Modes)



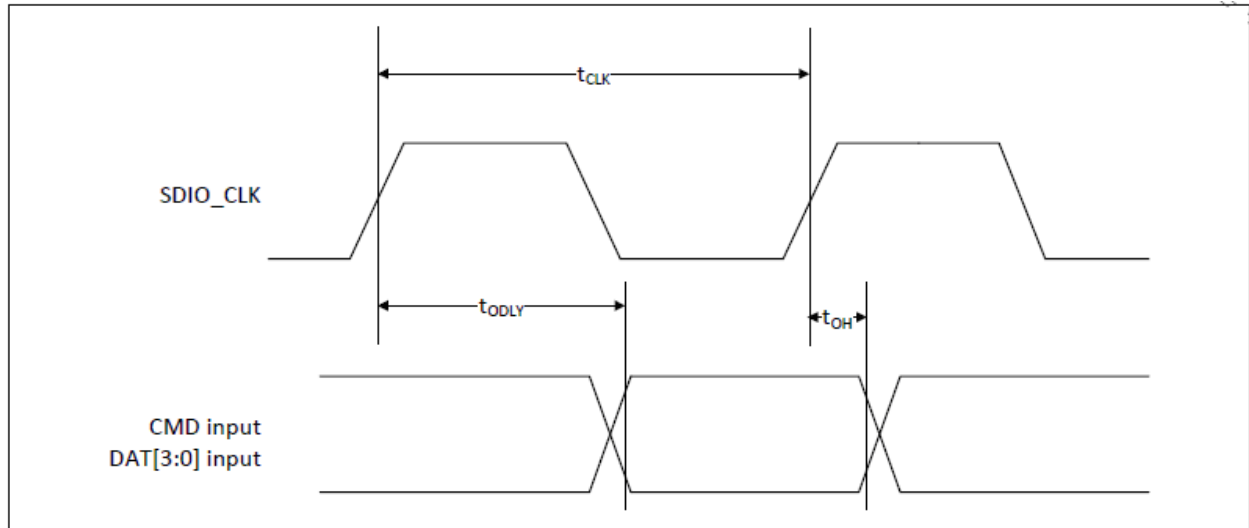
Parameter	Symbol	Minimum	Maximum	Unit	Comments
–	t_{CLK}	40	–	ns	SDR12 mode
		20	–	ns	SDR25 mode
		10	–	ns	SDR50 mode
		4.8	–	ns	SDR104 mode
–	t_{CR}, t_{CF}	–	$0.2 \times t_{CLK}$	ns	$t_{CR}, t_{CF} < 2.00$ ns (max) @100 MHz, $C_{CARD} = 10$ pF $t_{CR}, t_{CF} < 0.96$ ns (max) @208 MHz, $C_{CARD} = 10$ pF
Clock duty	–	30	70	%	–

SDIO Bus Input timing (SDR Modes)



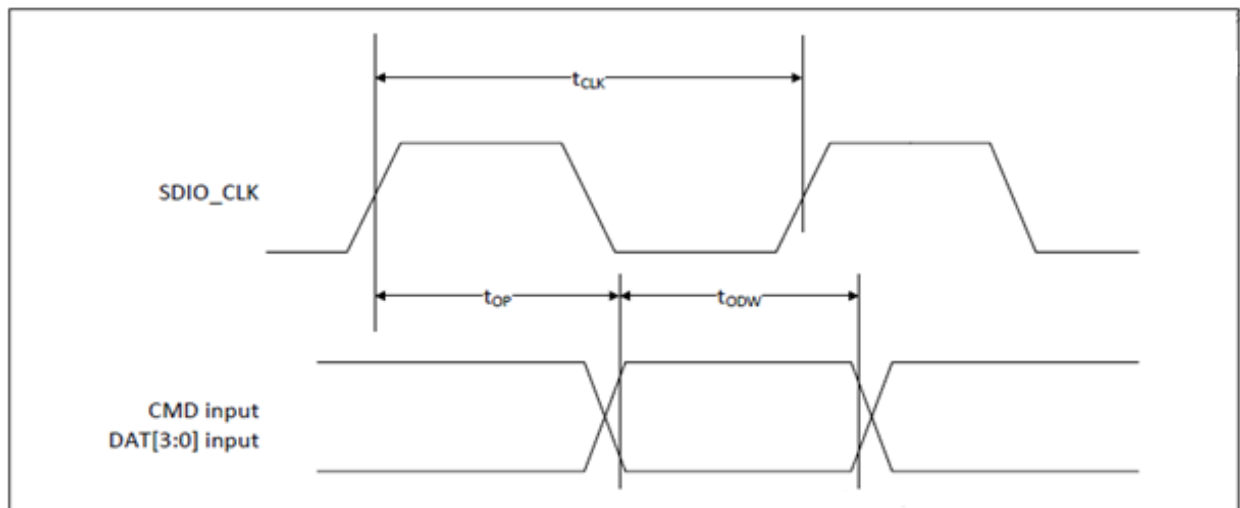
Symbol	Minimum	Maximum	Unit	Comments
SDR104 Mode				
t_{IS}	1.4	–	ns	$C_{CARD} = 10$ pF, VCT = 0.975V
t_{IH}	0.80	–	ns	$C_{CARD} = 5$ pF, VCT = 0.975V
SDR50 Mode				
t_{IS}	3.00	–	ns	$C_{CARD} = 10$ pF, VCT = 0.975V
t_{IH}	0.80	–	ns	$C_{CARD} = 5$ pF, VCT = 0.975V

SDIO Bus output timing (SDR Modes up to 100MHz)



Symbol	Minimum	Maximum	Unit	Comments
t_{ODLY}	–	7.5	ns	$t_{CLK} \geq 10$ ns $C_L = 30$ pF using driver type B for SDR50
t_{ODLY}	–	14.0	ns	$t_{CLK} \geq 20$ ns $C_L = 40$ pF using for SDR12, SDR25
t_{OH}	1.5	–	ns	Hold time at the t_{ODLY} (min) $C_L = 15$ pF

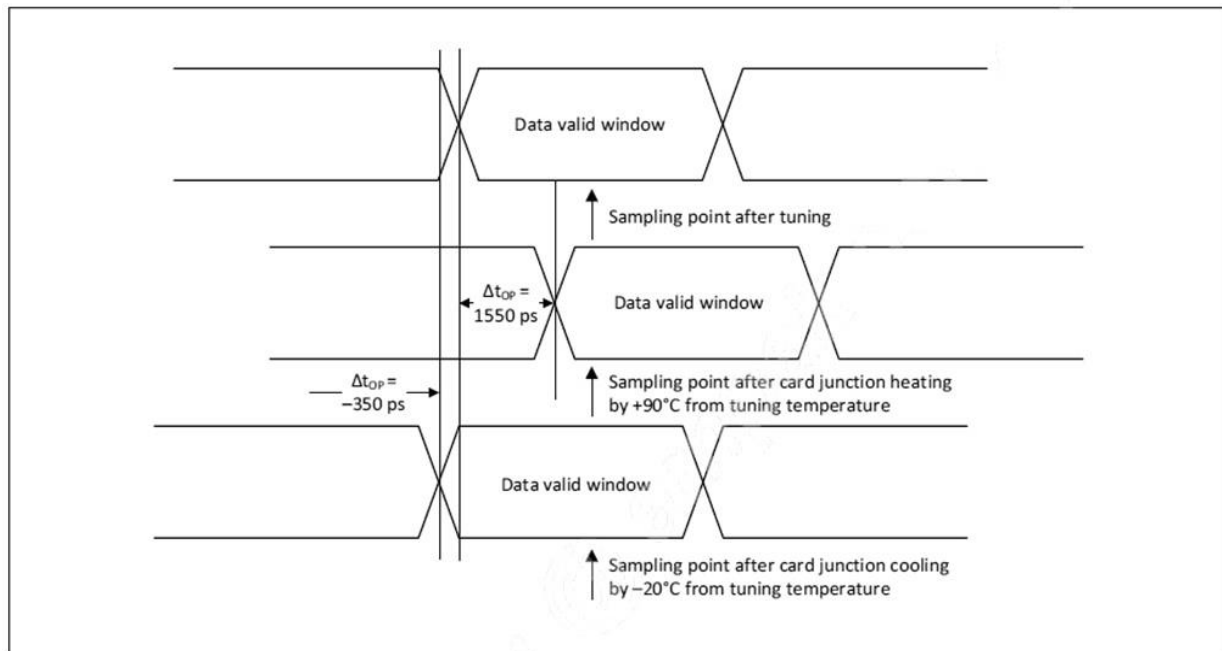
Card output timing (SDR Modes 100MHz to 208MHz)



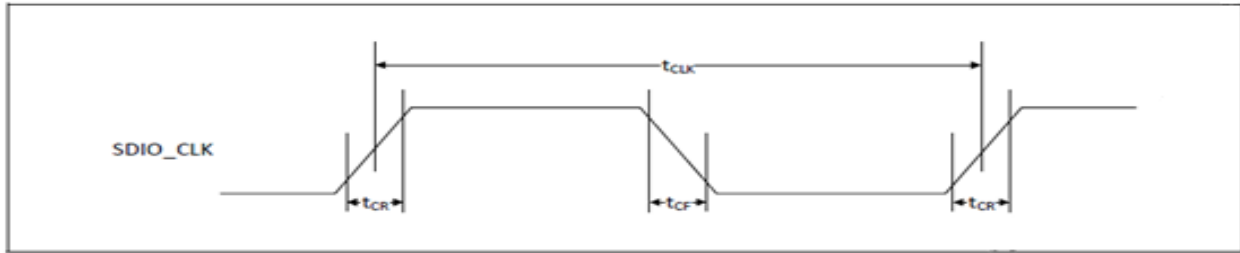
Symbol	Minimum	Maximum	Unit	Comments
t_{OP}	0	2	UI	Card output phase
Δt_{OP}	-350	+1550	ps	Delay variation due to temp change after tuning
t_{ODW}	0.60	—	UI	$t_{ODW}=2.88$ ns @208 MHz

- $\Delta t_{OP} = +1550$ ps for junction temperature of $\Delta t_{OP} = 90$ degrees during operation
- $\Delta t_{OP} = -350$ ps for junction temperature of $\Delta t_{OP} = -20$ degrees during operation
- $\Delta t_{OP} = +2600$ ps for junction temperature of $\Delta t_{OP} = -20$ to $+125$ degrees during operation

Δt_{OP} Consideration for Variable Data Window (SDR 104 Mode)

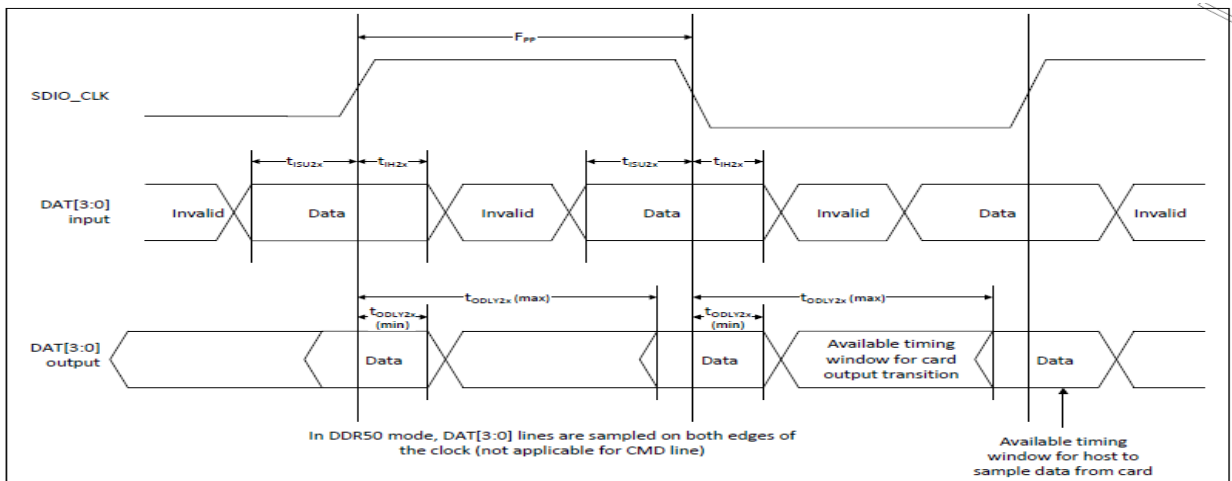


SDIO Bus Timing Specifications in DDR50 Mode



Parameter	Symbol	Minimum	Maximum	Unit	Comments
—	t_{CLK}	20	—	ns	DDR50 mode
—	t_{CR}, t_{CF}	—	$0.2 \times t_{CLK}$	ns	$t_{CR}, t_{CF} < 4.00$ ns (max) @50 MHz, $C_{CARD} = 10$ pF
Clock duty	—	45	55	%	—

Data Timing



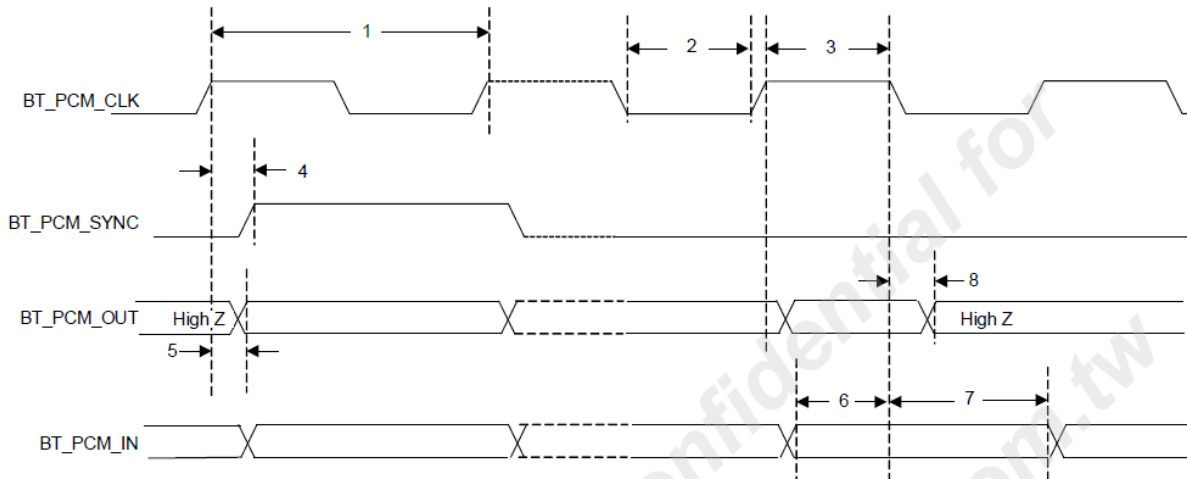
Parameter	Symbol	Minimum	Maximum	Unit	Comments
Input CMD					
Input setup time	t_{ISU}	6	—	ns	$C_{CARD} < 10$ pF (1 Card)
Input hold time	t_{IH}	0.8	—	ns	$C_{CARD} < 10$ pF (1 Card)
Output CMD					
Output delay time	t_{ODLY}	—	13.7	ns	$C_{CARD} < 30$ pF (1 Card)
Output hold time	t_{OH}	1.5	—	ns	$C_{CARD} < 15$ pF (1 Card)
Input DAT					
Input setup time	t_{ISU2x}	3	—	ns	$C_{CARD} < 10$ pF (1 Card)
Input hold time	t_{IH2x}	0.8	—	ns	$C_{CARD} < 10$ pF (1 Card)
Output DAT					
Output delay time	t_{ODLY2x}	—	7.5	ns	$C_{CARD} < 25$ pF (1 Card)
Output hold time	t_{ODLY2x}	1.5	—	ns	$C_{CARD} < 15$ pF (1 Card)

7.3 PCM Interface Description

AP6676SDSR supports two independent PCM interfaces that share the pins with the I²S interfaces. The PCM interface can connect to linear PCM codec devices in master or slave mode. In master mode, generates the BT_PCM_CLK and BT_PCM_SYNC signals, and in slave mode, these signals are provided by another master on the PCM interface and are inputs to the AP6676SDSR.

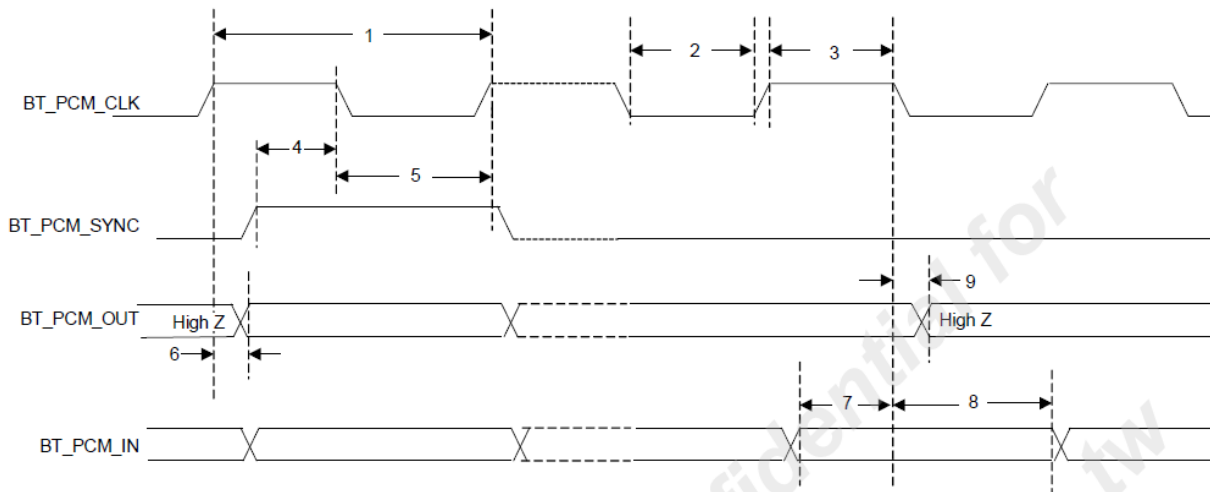
PCM Timing

Short Frame Sync, Master Mode



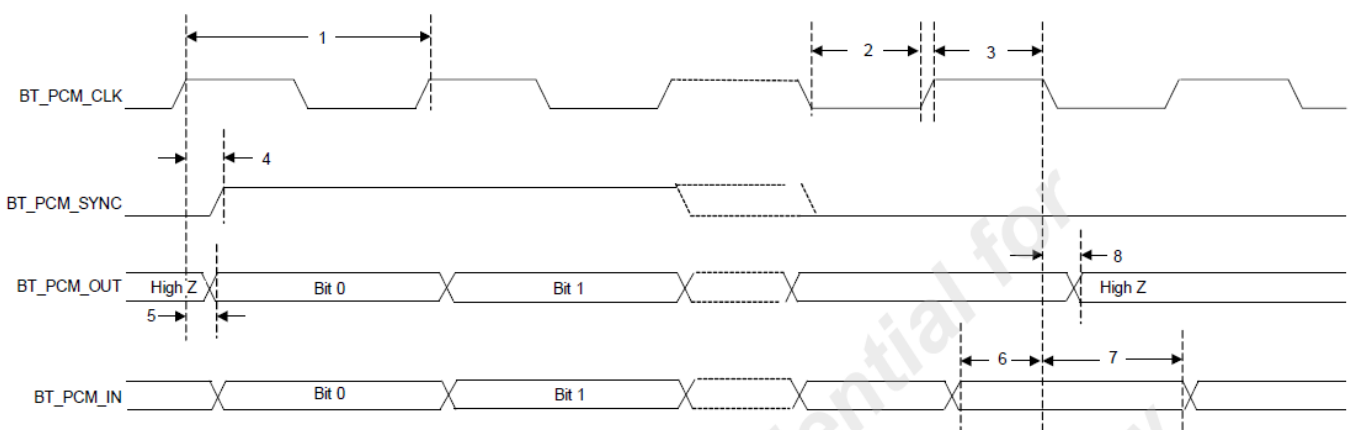
Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	—	—	12	MHz
2	PCM bit clock low	41	—	—	ns
3	PCM bit clock high	41	—	—	ns
4	BT_PCM_SYNC delay	0	—	25	ns
5	BT_PCM_OUT delay	0	—	25	ns
6	BT_PCM_IN setup	8	—	—	ns
7	BT_PCM_IN hold	8	—	—	ns
8	Delay from falling edge of BT_PCM_CLK during the last bit period to BT_PCM_OUT becoming high impedance.	0	—	25	ns

Short Frame Sync, Slave Mode



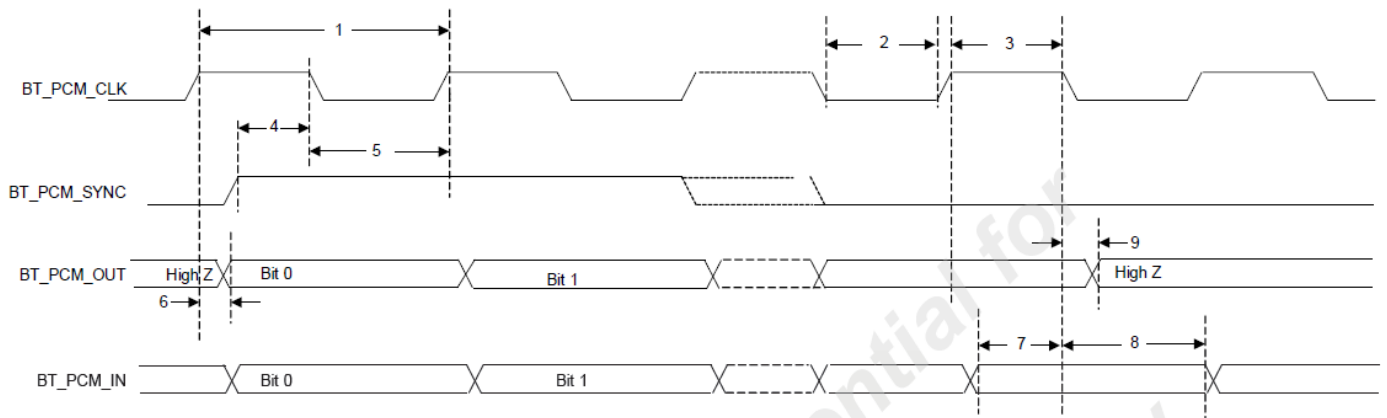
Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	—	—	12	MHz
2	PCM bit clock low	41	—	—	ns
3	PCM bit clock high	41	—	—	ns
4	BT_PCM_SYNC setup	8	—	—	ns
5	BT_PCM_SYNC hold	8	—	—	ns
6	BT_PCM_OUT delay	0	—	25	ns
7	BT_PCM_IN setup	8	—	—	ns
8	BT_PCM_IN hold	8	—	—	ns
9	Delay from falling edge of BT_PCM_CLK during the last bit period to BT_PCM_OUT becoming high impedance.	0	—	25	ns

Long Frame Sync, Master Mode



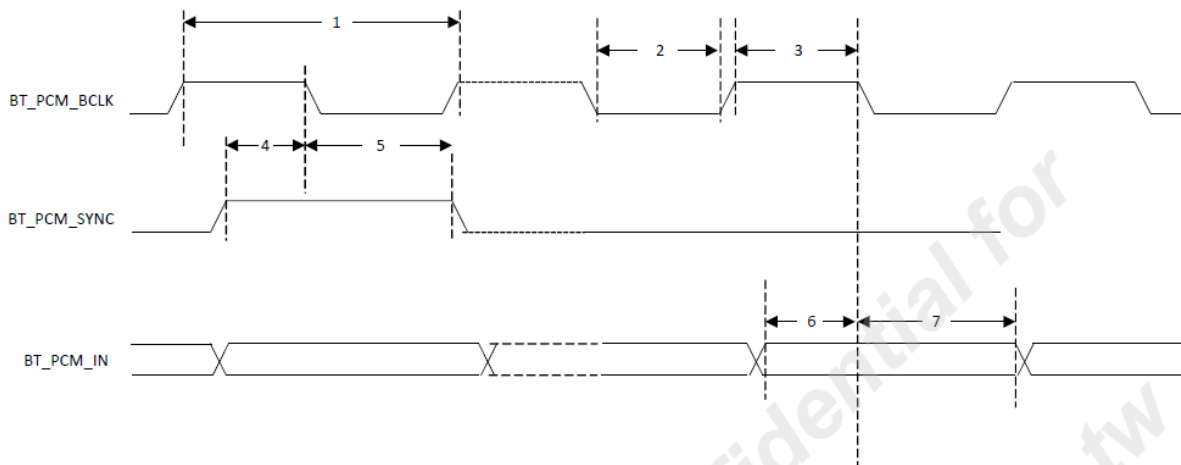
Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	—	—	12	MHz
2	PCM bit clock low	41	—	—	ns
3	PCM bit clock high	41	—	—	ns
4	BT_PCM_SYNC delay	0	—	25	ns
5	BT_PCM_OUT delay	0	—	25	ns
6	BT_PCM_IN setup	8	—	—	ns
7	BT_PCM_IN hold	8	—	—	ns
8	Delay from falling edge of BT_PCM_CLK during the last bit period to BT_PCM_OUT becoming high impedance.	0	—	25	ns

Long Frame Sync, Slave Mode



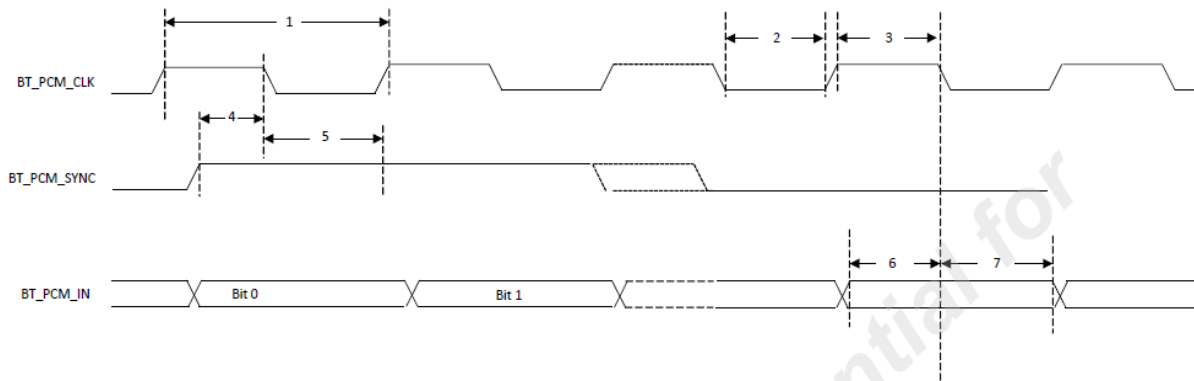
Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	—	—	12	MHz
2	PCM bit clock low	41	—	—	ns
3	PCM bit clock high	41	—	—	ns
4	BT_PCM_SYNC setup	8	—	—	ns
5	BT_PCM_SYNC hold	8	—	—	ns
6	BT_PCM_OUT delay	0	—	25	ns
7	BT_PCM_IN setup	8	—	—	ns
8	BT_PCM_IN hold	8	—	—	ns
9	Delay from falling edge of BT_PCM_CLK during the last bit period to BT_PCM_OUT becoming high impedance.	0	—	25	ns

Short Frame Sync, Burst Mod



Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	—	—	24	MHz
2	PCM bit clock low	20.8	—	—	ns
3	PCM bit clock high	20.8	—	—	ns
4	BT_PCM_SYNC setup	8	—	—	ns
5	BT_PCM_SYNC hold	8	—	—	ns
6	BT_PCM_IN setup	8	—	—	ns
7	BT_PCM_IN hold	8	—	—	ns

Long Frame Sync, Burst Mode

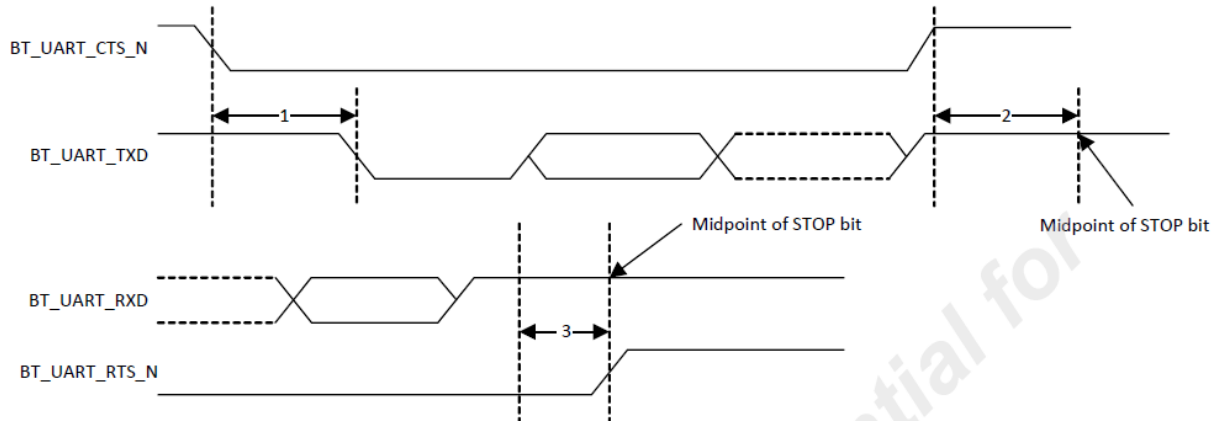


Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	—	—	24	MHz
2	PCM bit clock low	20.8	—	—	ns
3	PCM bit clock high	20.8	—	—	ns
4	BT_PCM_SYNC setup	8	—	—	ns
5	BT_PCM_SYNC hold	8	—	—	ns
6	BT_PCM_IN setup	8	—	—	ns
7	BT_PCM_IN hold	8	—	—	ns

7.4 UART Interface Description

The AP6676SDSR UART is a standard 4-wire interface with adjustable baud rates from 9600 bps to 4.0 Mbps. The interface features an automatic baud rate detection capability that returns a baud rate selection. Alternatively, the baud rate may be selected through a vendor-specific UART HCI command.

UART Timing

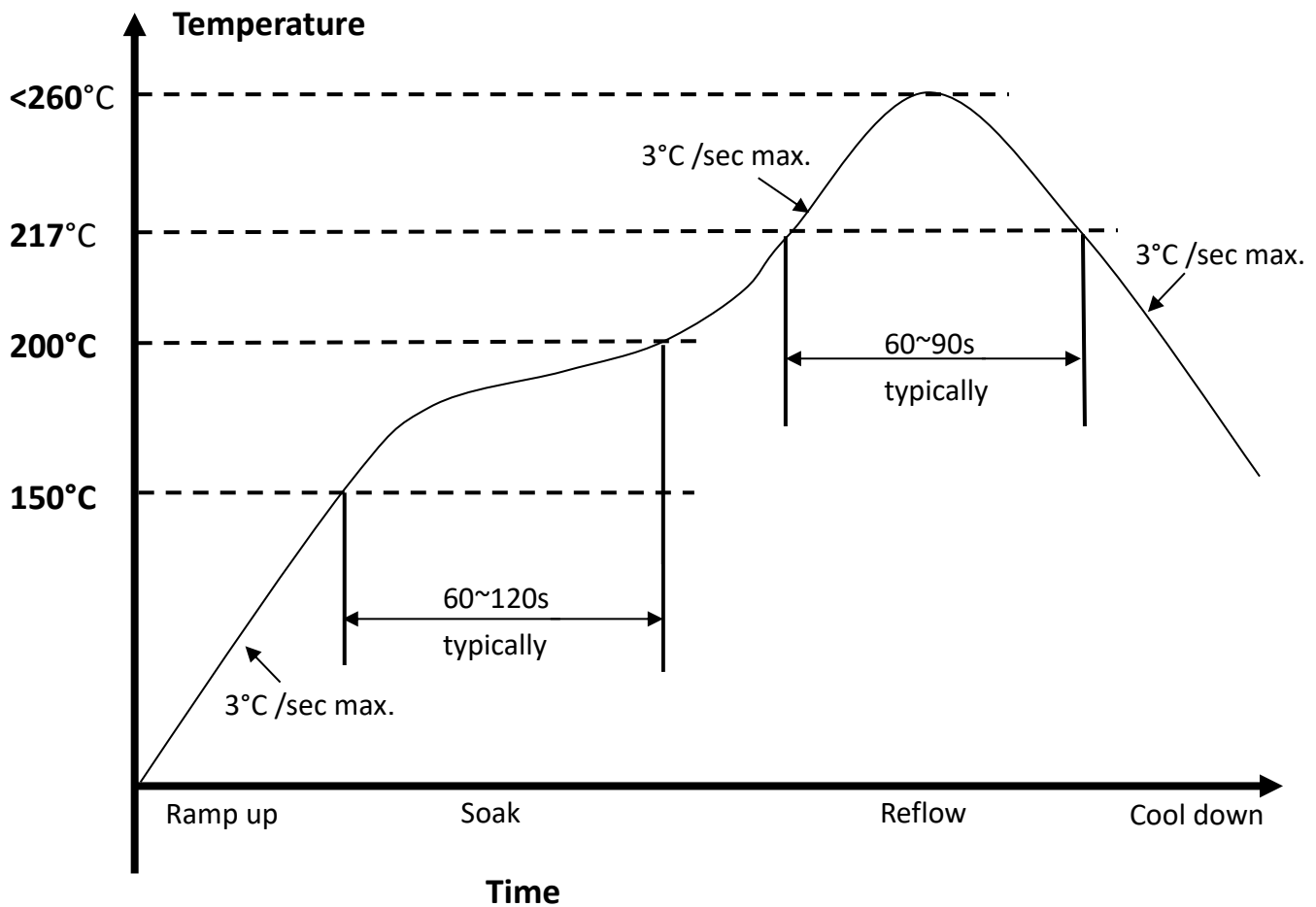


Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	Delay time, BT_UART_CTS_N low to BT_UART_TXD valid	—	—	1.5	Bit periods
2	Setup time, BT_UART_CTS_N high before midpoint of stop bit	—	—	0.5	Bit periods
3	Delay time, midpoint of stop bit to BT_UART_RTS_N high	—	—	0.5	Bit periods

7.5 External LPO Signal Characteristics

Parameter	Specification	Units
Nominal input frequency	32.768	kHz
Frequency accuracy	+/-25	ppm
Duty cycle	30 - 70	%
Input signal amplitude	1.8±0.09	V
Signal type	Square-wave	-
Input impedance	>100k <5	Ω pF
Clock jitter (integrated over 300Hz – 15KHz)	<1	Hz
Output high voltage	0.7V _{io} - V _{io}	V

8. Recommended Reflow Profile



1. Referred to IPC/JEDEC standard
2. Peak Temperature : <260°C (Time within 5°C of actual Peak Temperature 20-40 seconds)
3. Cycle of Reflow : 2 times max.
4. Adding Nitrogen (N₂) to implement 2000ppm or less of oxygen concentration during reflow process is recommended.
5. If the shelf time is exceeded, be sure baking step to remove the moisture from the component

9. Package Information

9.1 Label

Label A → Anti-static and humidity notice



Label B → MSL caution / Storage Condition

Caution		LEVEL
This bag contains MOISTURE-SENSITIVE DEVICES		☐
		If blank, see adjacent bar code label
1. Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)		
2. Peak package body temperature: _____ °C If blank, see adjacent bar code label		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be		
a) Mounted within: _____ hours of factory conditions If blank, see adjacent bar code label		
b) Stored per J-STD-033		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at 23 ± 5°C		
b) 3a or 3b are not met		
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: _____ If blank, see adjacent bar code label		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		

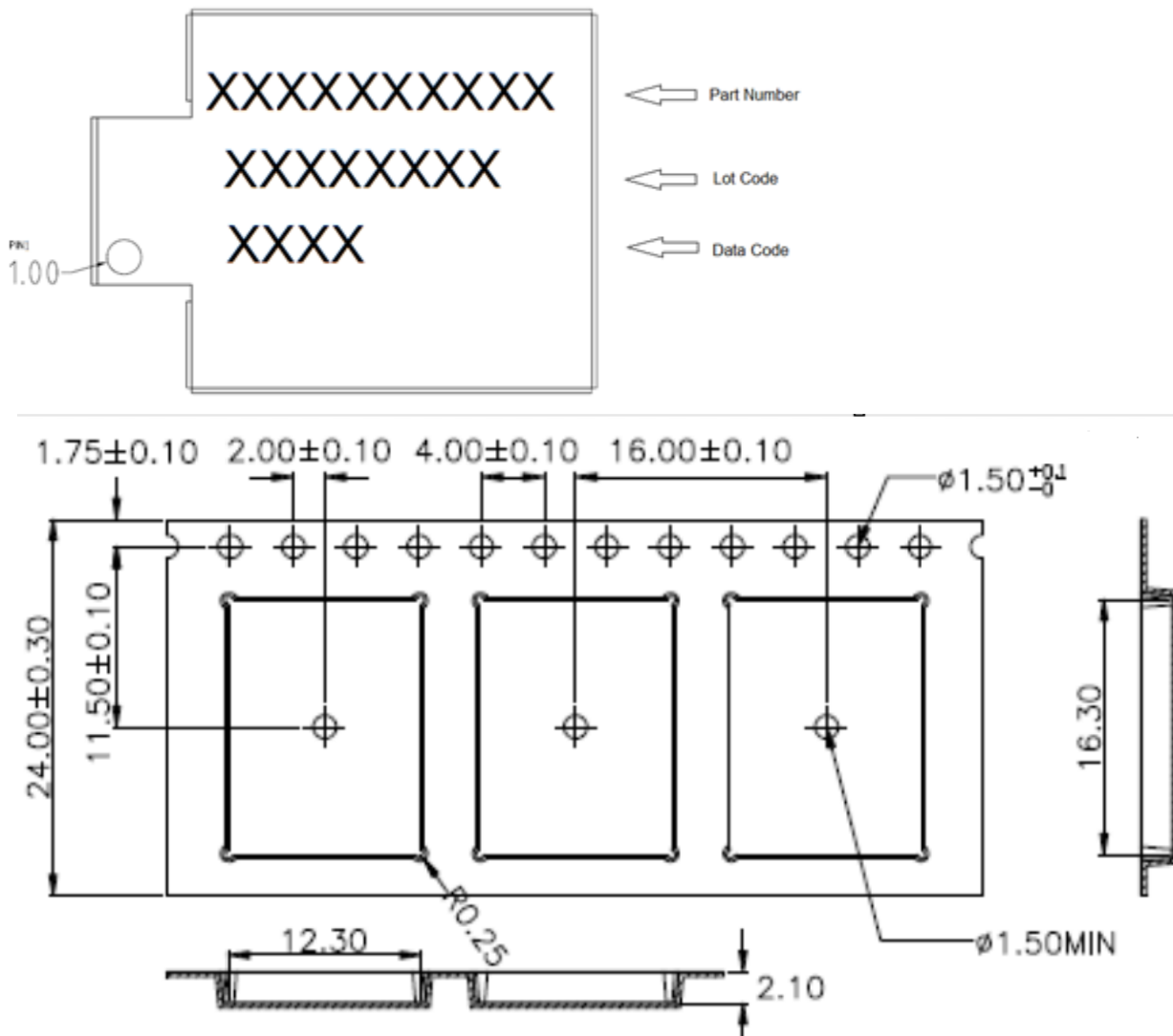
Label C → Inner box label

(1T)PKG S/N:	TPKGYMMDDnnnnn	
PO:	NA	
(P)Model Name:	AP6676SDSR (R3HF)	
(1P)P/N:	99P-W01-0784R	
51P P/N:	NA	
(L)Lot Code:	XXXXXXXXX	
(D)Date Code:	YYWW	
(Q)Quantity:	QQQQ	
Product size:	16x12mm	
MSL:	4	
Made in	Taiwan	
RoHS		H/F

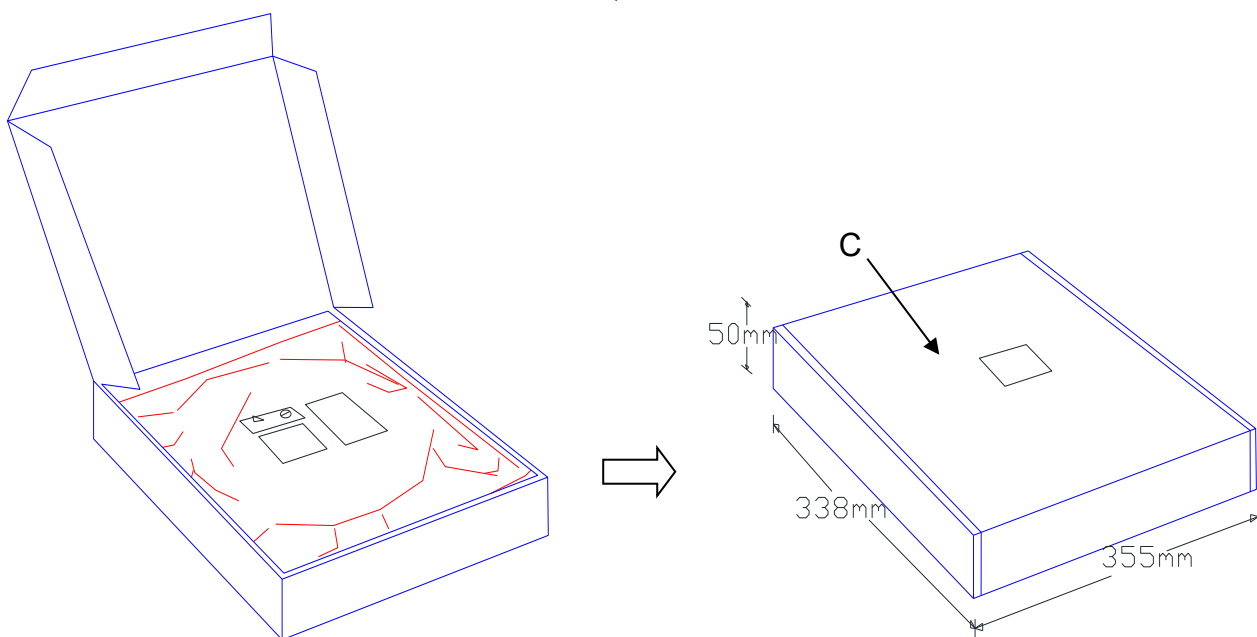
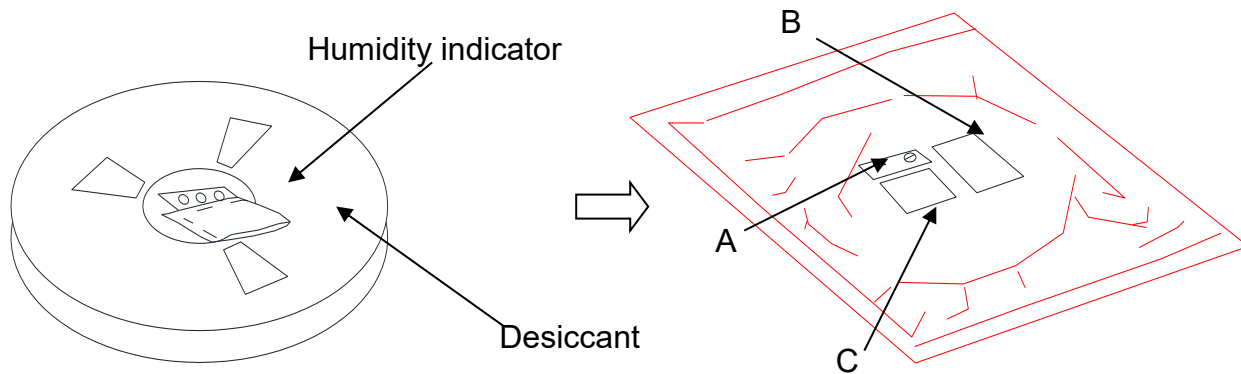
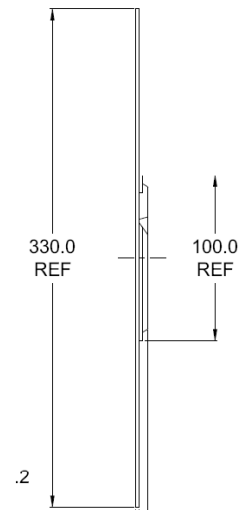
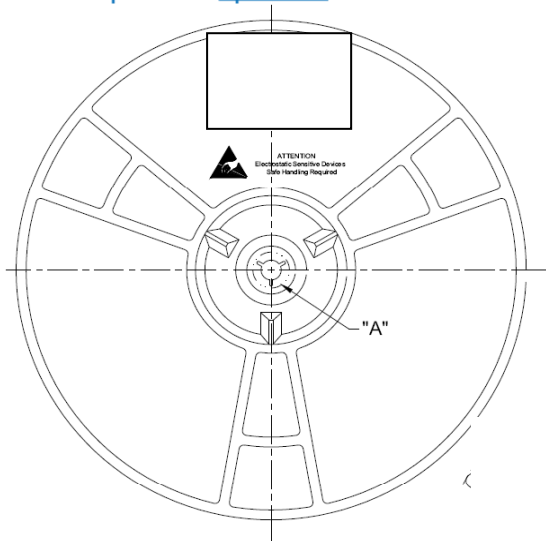
Label D → Carton box label .

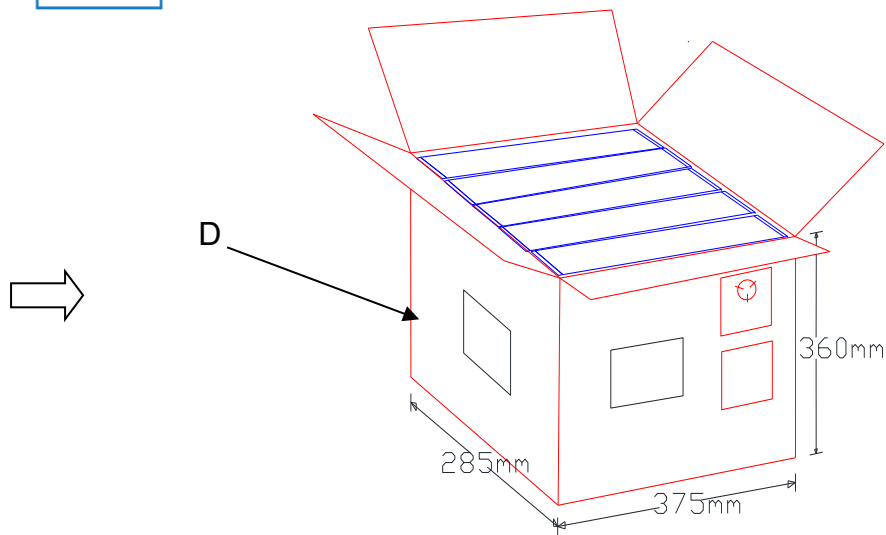
AMPAK Technology Inc.	
(1T)Carton No.:	CTYYMMDDXXQQXX
PO:	NA
(P)Model Name:	AP6676SDSR (R3HF)
(1P)P/N:	99P-W01-0784R
YEKER P/N:	NA
(LD)Lot D/C:	TPKGYMMDDnnnnn XXXXXXXXX YYWW QQQQ
(Q)Quantity:	QQQQ
Manufacture:	YYYY/MM/DD
Product size:	16x12mm
MSL:	4
Made in	Taiwan
RoHS H/F	

9.2 Dimension



1. 10 sprocket hole pitch cumulative tolerance ± 0.20 .
2. Carrier camber is within 1 mm in 250 mm.
3. Material : Black Conductive Polystyrene Alloy.
4. All dimensions meet EIA-481-D requirements.
5. Thickness: 0.30 ± 0.05 mm.
6. Component load per 13" reel : 1000 pcs





9.3 MSL Level / Storage Condition

	Caution This bag contains MOISTURE-SENSITIVE DEVICES	LEVEL
		4 If blank, see adjacent bar code label
1. Calculated shelf life in sealed bag: 12 months at $<40^{\circ}\text{C}$ and $<90\%$ relative humidity (RH)		
2. Peak package body temperature: <u>250</u> $^{\circ}\text{C}$ If blank, see adjacent bar code label		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be		
a) Mounted within: <u>72</u> hours of factory conditions If blank, see adjacent bar code label		
$\leq 30^{\circ}\text{C}/60\% \text{ RH}$, or		
b) Stored per J-STD-033		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card reads $>10\%$ for level 2a-5a devices or $>60\%$ for level 2 devices when read at $23 \pm 5^{\circ}\text{C}$		
b) 3a or 3b are not met.		
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure.		
Bag Seal Date: _____ If blank, see adjacent bar code label		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		

FCC Statement

This device complies with part 15 of the FCC rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help important announcement

Important Note:

Radiation Exposure Statement

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator and your body.

This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

Country Code selection feature to be disabled for products marketed to the US/Canada.

This device is intended only for OEM integrators under the following conditions:

1. The antenna must be installed such that 20 cm is maintained between the antenna and users, and
2. The transmitter module may not be co-located with any other transmitter or antenna,
3. For all products market in US, OEM has to limit the operation channels in CH1 to CH11 for 2.4G band by supplied firmware programming tool. OEM shall not supply any tool or info to the end-user regarding to Regulatory Domain change. (if modular only test Channel 1-11)

As long as the three conditions above are met, further transmitter testing will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

Important Note:

In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

End Product Labeling

The final end product must be labeled in a visible area with the following"

Contains **FCC ID: RYK-WNFS-267AXIBT** "

Manual Information to the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module.

The end user manual shall include all required regulatory information/warning as show in this manual.

Integration instructions for host product manufacturers according to KDB 996369 D03 OEM Manual v01r01

2.2 List of applicable FCC rules

CFR 47 FCC PART 15 SUBPART C has been investigated. It is applicable to the modular transmitter

2.3 Specific operational use conditions

This module is stand-alone modular. If the end product will involve the Multiple simultaneously transmitting condition or different operational conditions for a stand-alone modular transmitter in a host, host manufacturer have to consult with module manufacturer for the installation method in end system.

2.4 Limited module procedures

Not applicable

2.5 Trace antenna designs

Not applicable

2.6 RF exposure considerations

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body.

2.7 Antennas

This radio transmitter **FCC ID: RYK-WNFS-267AXIBT** has been approved by Federal Communications Commission to operate with the antenna types listed below, with the maximum permissible gain indicated. Antenna types not included in this list that have a gain greater than the maximum gain indicated for any type listed are strictly prohibited for use with this device.

BT&2.4GWIFI

Model No. of antenna:	Type of antenna:	Gain of the antenna (Max.)	
		Antenna 1	Antenna 2
AD-103AG	Dipole Antenna	2.02dBi	2.02dBi
AD-301N	Dipole Antenna	4.4dBi	4.4dBi
AD-302N	Dipole Antenna	3.14dBi	3.14dBi
AD-303N	Dipole Antenna	3.14dBi	3.14dBi
AD-305N	Dipole Antenna	5.0dBi	5.0dBi
AD-501AX	Dipole Antenna	3.7dBi	3.7dBi
AD-510AX	Dipole Antenna	2.27dBi	2.27dBi
AD-512AX	Dipole Antenna	2.35dBi	2.35dBi
AD-514AX	Dipole Antenna	3.07dBi	3.07dBi
AD-515AX	Dipole Antenna	5.96dBi	5.96dBi

5G WIFI

Model No. of antenna:	Type of antenna:	Gain of the antenna (Max.)	
		Antenna 1	Antenna 2
AD-103AG	Dipole Antenna	2.03dBi	2.03dBi
AD-301N	Dipole Antenna	5.8dBi	5.8dBi
AD-302N	Dipole Antenna	2.87dBi	2.87dBi
AD-303N	Dipole Antenna	3.45dBi	3.45dBi
AD-305N	Dipole Antenna	5.53dBi	5.53dBi
AD-501AX	Dipole Antenna	5.0dBi	5.0dBi
AD-510AX	Dipole Antenna	3.52dBi	3.52dBi
AD-512AX	Dipole Antenna	3.02dBi	3.02dBi
AD-514AX	Dipole Antenna	4.17dBi	4.17dBi
AD-515AX	Dipole Antenna	6.34dBi	6.34dBi

6G WIFI

Model No. of antenna:	Type of antenna:	Gain of the antenna (Max.)	
		Antenna 1	Antenna 2
AD-501AX	Dipole Antenna	5.0dBi	5.0dBi
AD-510AX	Dipole Antenna	3.52dBi	3.52dBi
AD-512AX	Dipole Antenna	3.02dBi	3.02dBi
AD-514AX	Dipole Antenna	4.17dBi	4.17dBi
AD-515AX	Dipole Antenna	6.34dBi	6.34dBi

2.8 Label and compliance information

The final end product must be labeled in a visible area with the following" Contains **FCC ID: RYK-WNFS-267AXIBT**".

2.9 Information on test modes and additional testing requirements

Host manufacturer is strongly recommended to confirm compliance with FCC requirements for the transmitter when the module is installed in the host.

2.10 Additional testing, Part 15 Subpart B disclaimer

Host manufacturer is responsible for compliance of the host system with module installed with all other applicable requirements for the system such as Part 15 B.

2.11 Note EMI Considerations

Host manufacture is recommended to use D04 Module Integration Guide recommending as "best practice" RF design engineering testing and evaluation in case non-linear interactions generate additional non-compliant limits due to module placement to host components or properties.

2.12 How to make changes

This module is stand-alone modular. If the end product will involve the Multiple simultaneously transmitting condition or different operational conditions for a stand-alone modular transmitter in a host, host manufacturer have to consult with module manufacturer for the installation method in end system. According to the KDB 996369 D02 Q&A Q12, that a host manufacture only needs to do an evaluation (i.e., no C2PC required when no emission exceeds the limit of any individual device (including unintentional radiators) as a composite. The host manufacturer must fix any failure.

Transmitters in the 5.925-7.125 GHz band are prohibited from operating to control or communicate with unmanned aircraft systems.

ISED Statement

- English: This device contains licence-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada's licence-exempt RSS(s). Operation is subject to the following two conditions:

(1) This device may not cause interference.

(2) This device must accept any interference, including interference that may cause undesired operation of the device.

- French: Cet appareil contient des émetteurs/récepteurs exempts de licence qui sont conformes aux CNR exempts de licence d'Innovation, Sciences et Développement économique Canada. Le fonctionnement est soumis aux deux conditions suivantes :

(1) Cet appareil ne doit pas causer d'interférences.

(2) Cet appareil doit accepter toute interférence, y compris les interférences susceptibles de provoquer un fonctionnement indésirable de l'appareil.

This device meets the exemption from the routine evaluation limits in section 6.3 of RSS 102 and compliance with RSS 102 RF exposure, users can obtain Canadian information on RF exposure and compliance.

cet appareil est conforme à l'exemption des limites d'évaluation courante dans la section 6.3 du cnr - 102 et conformité avec rss 102 de l'exposition aux rf, les utilisateurs peuvent obtenir des données canadiennes sur l'exposition aux champs rf et la conformité.

This equipment complies with Canada radiation exposure limits set forth for an uncontrolled environment.

This equipment should be installed and operated with minimum distance 20cm between the radiator & your body.

Cet équipement est conforme Canada limites d'exposition aux radiations dans un environnement non contrôlé.

Cet équipement doit être installé et utilisé avec une distance minimale de 20 cm entre le radiateur et votre corps.

The device for operation in the band 5150–5250 MHz is only for indoor use to reduce the potential for harmful interference to cochannel mobile satellite systems.

L'appareil destiné à fonctionner dans la bande 5150-5250 MHz est uniquement destiné à une utilisation en intérieur afin de réduire le potentiel d'interférences nuisibles aux systèmes mobiles par satellite cocanaux.

RED2014/53/EU

Declaration of Conformity

Hereby, SparkLAN Communications, Inc. declares that this IEEE 802.11ax/ac/a/b/g/n 2x2 WiFi 6E with Bluetooth5.3 Combo Module product is in compliance with essential requirements and other relevant provisions of Directive 2014/53/EU. A copy of the Declaration of conformity can be found at <https://www.sparklan.com/>

The IEEE 802.11ax/ac/a/b/g/n 2x2 WiFi 6E with Bluetooth5.3 Combo Module used at 20cm from body.

When the device support wlan5G(5150-5250Mhz), Manufacture will list the following statement and country list (not EU country) on the user manual, and wlan 5G only used to indoor

The 6E band 5.925 - 6.425GHz is for Low Power in-door (LPI)

	AT	BE	BG	HR	CY	CZ	DK
	EE	FI	FR	DE	EL	HU	IE
	IT	LV	LT	LU	MT	NL	PL
	PT	RO	SK	SI	ES	SE	UK

Bluetooth: 9.83Bm(EIRP)

Bluetooth LE: 8.55dBm(EIRP)

2.4G WIFI: 19.5dBm(EIRP)

5G WIFI(Bnad1&2&3&): 20.35dBm(EIRP)

5G WIFI Band4: 13.94dBm(EIRP)

6G WIFI: 20.07dBm(EIRP)